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ST Silicon Carbide Products and Industrial Application Guide

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Agenda

1 About SiC material

2 ST SiC market overview

3 ST SiC diodes and feature

4 ST SiC MOSFETs

5 SiC MOSFET – switching and driving

6 New SiC related evalboards

7 ST support tools

About SiC material



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About SiC material

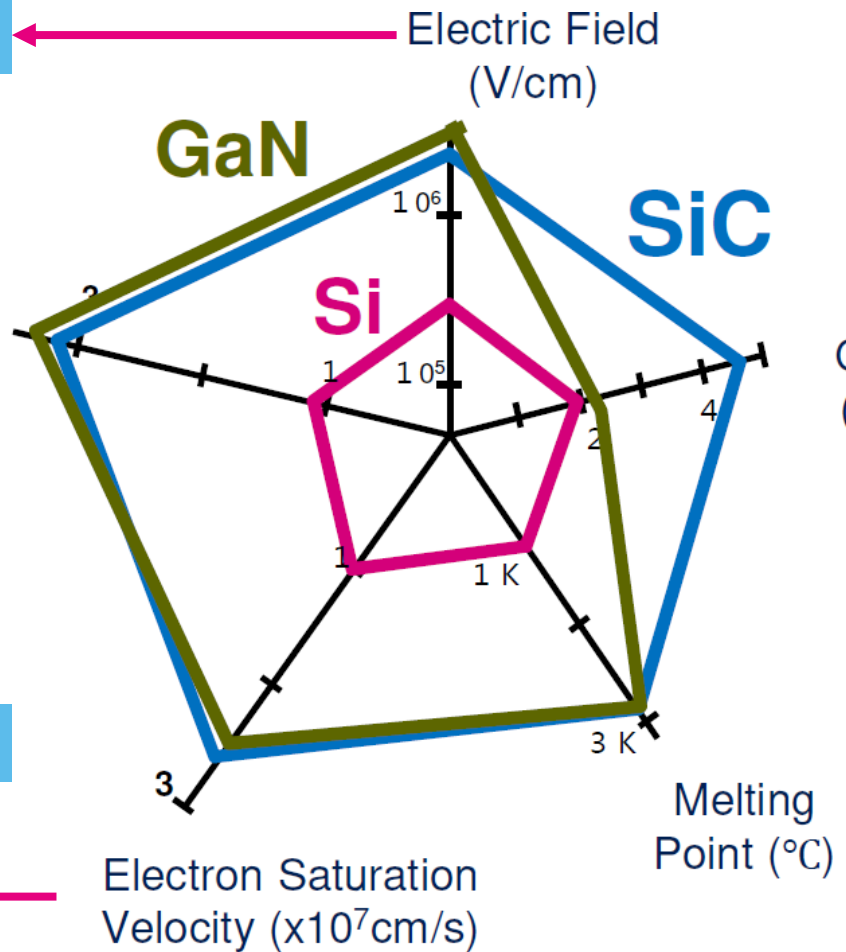
Lower ON Resistance & losses

Higher Break Down Voltage

Higher Switching Frequency

Better Thermal performance
Reduced Cooling requirements

Higher Junction Temperature
Up to 200°C



Key figures for SiC vs. Silicon

SiC Vs. Silicon Material Properties

 **1/300**
SiC Vs. Si
Resistivity
(At same applied Voltage)

 **x3** Thermal
Conductivity

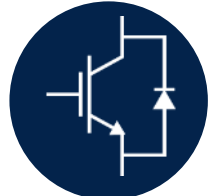
 Higher Thermal
Insensitivity


SiC Vs. IGBT Performance


 **-80%**
Switching Losses
mainly due to lower
Resistance



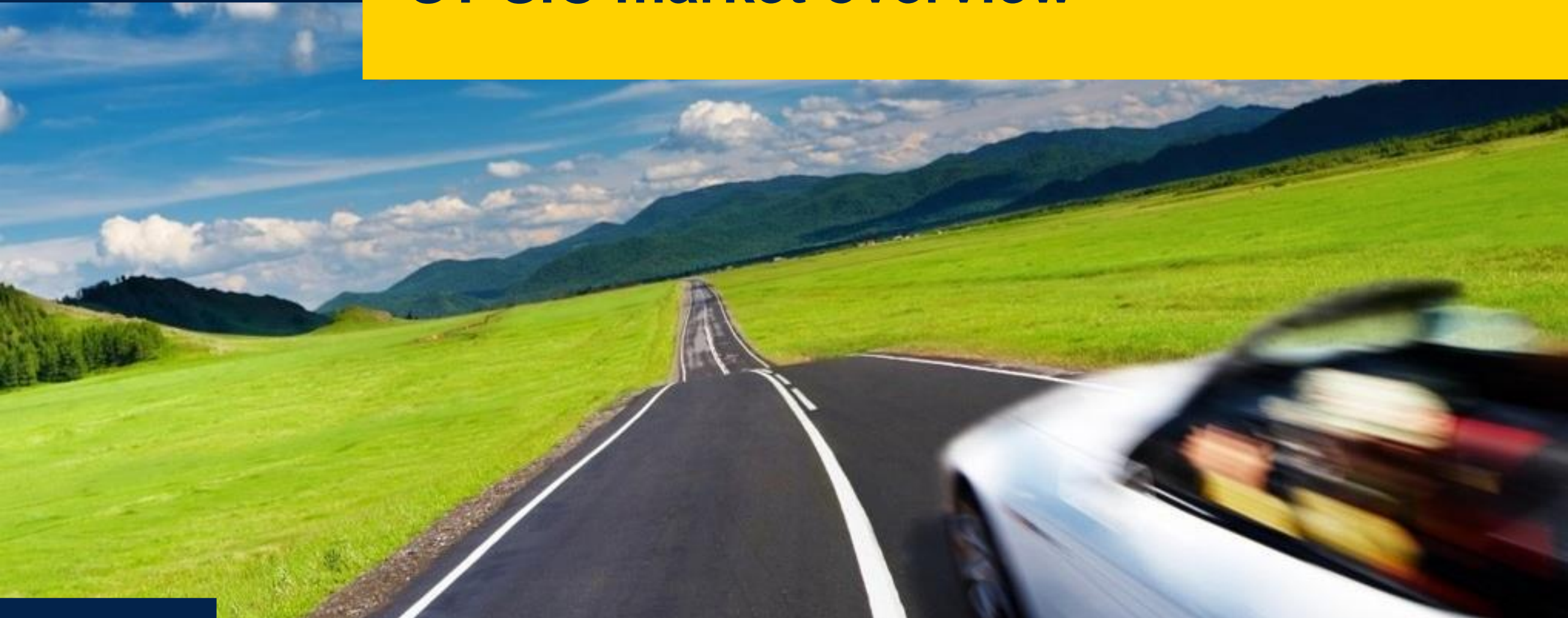
VS.



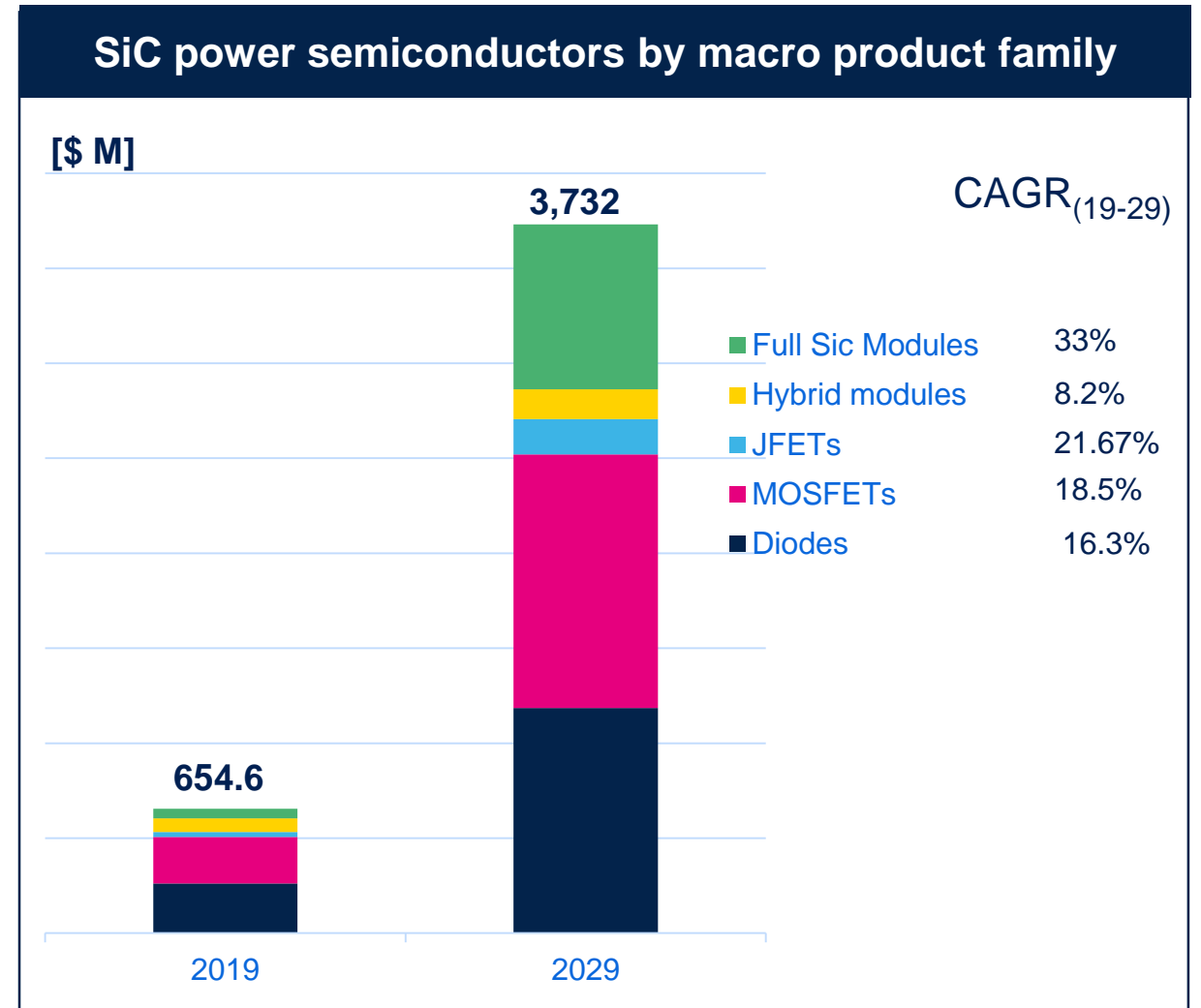
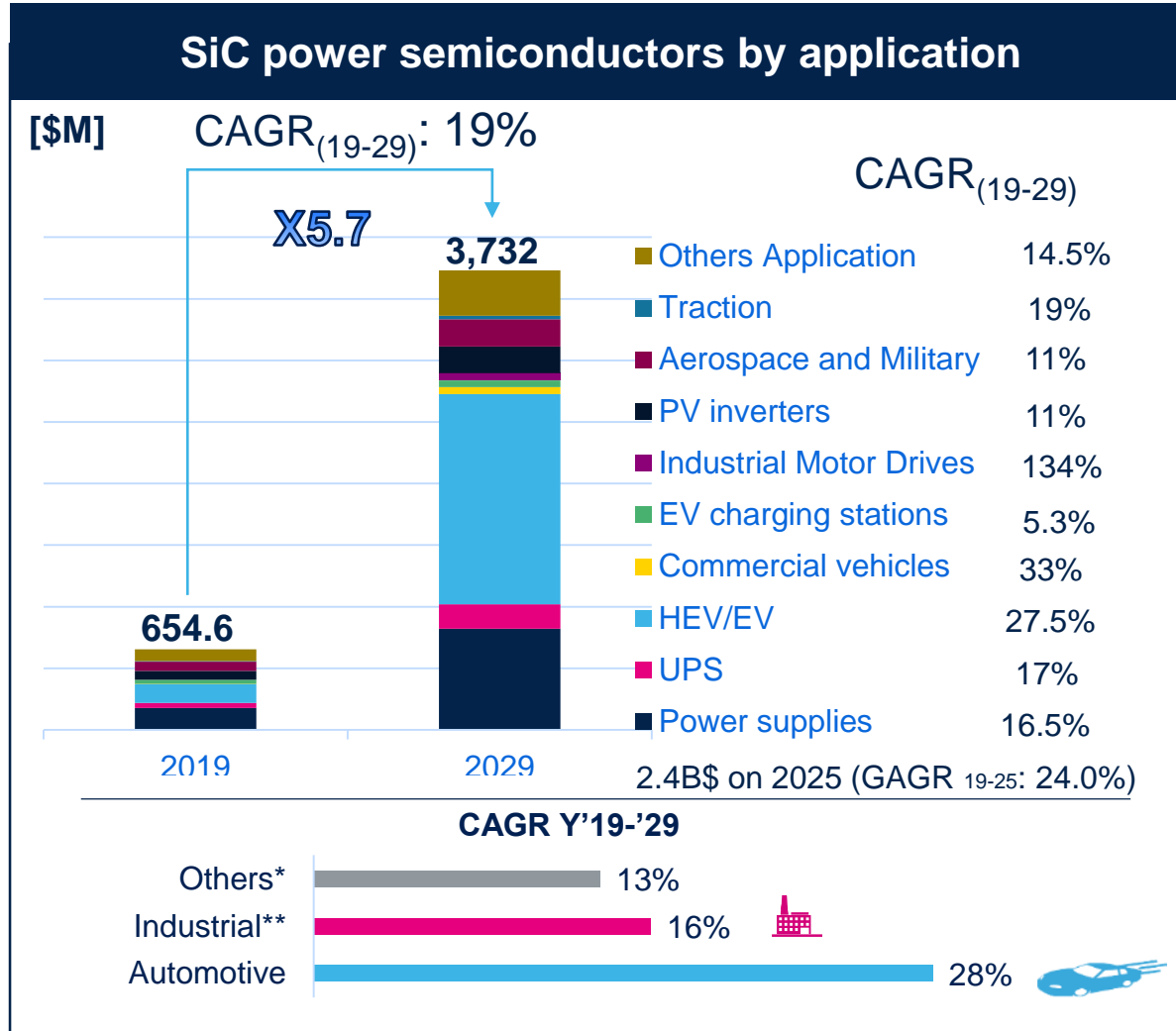
 **-80%**
Component
Weight

 **-85%**
Component
Volume Dimension

ST SiC market overview



Silicon Carbide market outlook



ST mastering all Silicon Carbide manufacturing steps

Pioneering WBG materials, with longer than 20 years commitment in R&D

Catania: Power Electronics Competence Center

Ecosystem made of Academic Research Centers and ST as a semiconductor leader, created a true "incubator"



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Consiglio Nazionale Ricerche

Everything started from 1" wafer

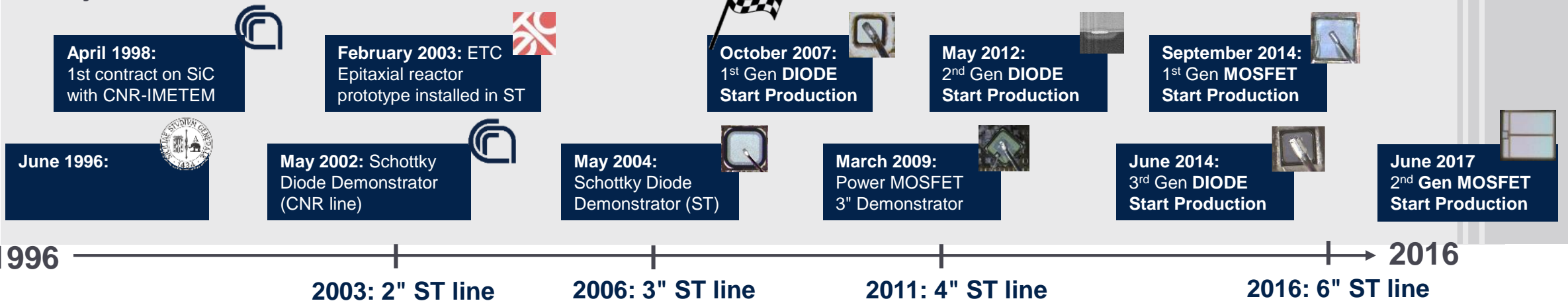
More Than 70 Patents on SiC

ST Commitment on SiC

Leveraging on CNR Facilities at early stage

> 30 Years Experience in Power Semiconductor

ST Major Milestones

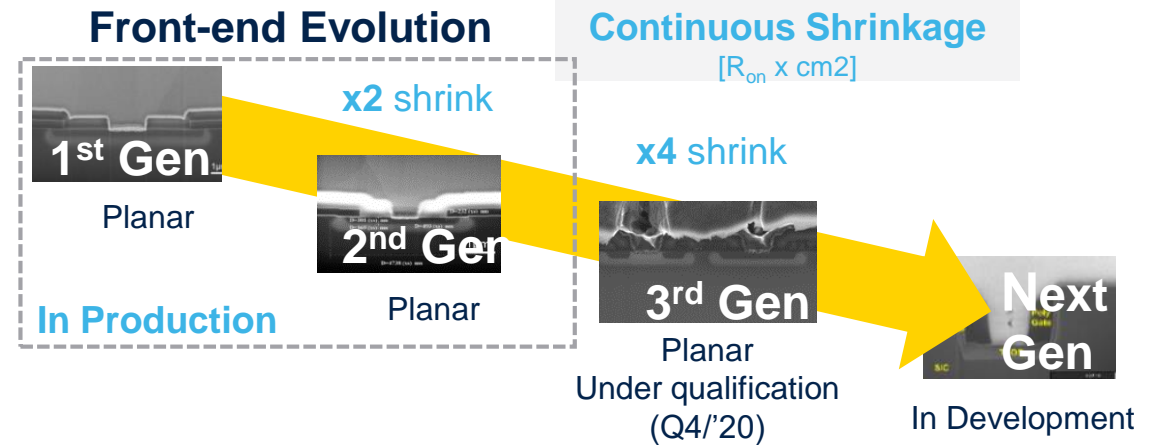




STPOWER Silicon Carbide MOSFETs

Best-in-class SiC Technology

- **ST broad range of SiC solutions:** Discrete, Bare Dice, Module
- **ST proven very high reliability**
- **ST continue capacity expansion** to support market acceleration
- **ST invests on advanced package technologies**



ST committed to develop its SiC Supply Chain

- **Vertical integration** through **Norstel AB** acquisition
- **Extended** supply chain capability through multi-year supply agreement
- Continue **to invest** to expand **ST capacity**



STPOWER SiC MOSFET focused market

Car Electrification

GROWTH DRIVERS

- Environment: WW CO₂ emission reduction program
- Car electrification huge growth trend
- Smaller and lighter power unit form factor
- Better Inverter efficiency SiC MOSFET vs. IGBT (extra mileage / lower battery cost)

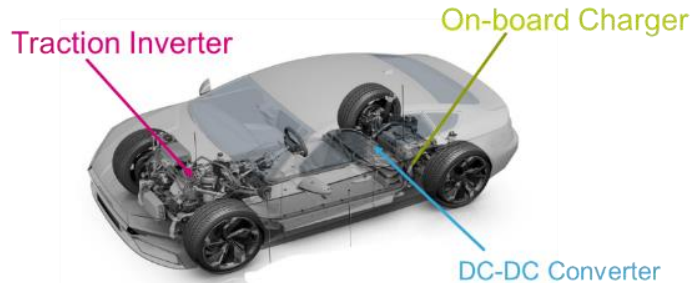
GROWTH DRIVERS

- Better efficiency
- Smaller form factor
- Lower TCO vs. silicon technologies

High End Industrial

KEY APPLICATIONS

- Traction Inverter
- OBC
- DC/DC Converter



KEY APPLICATIONS

- Solar Inverter
- Energy Storage
- Power Supply
- Charging Station
- Welding
- Drives

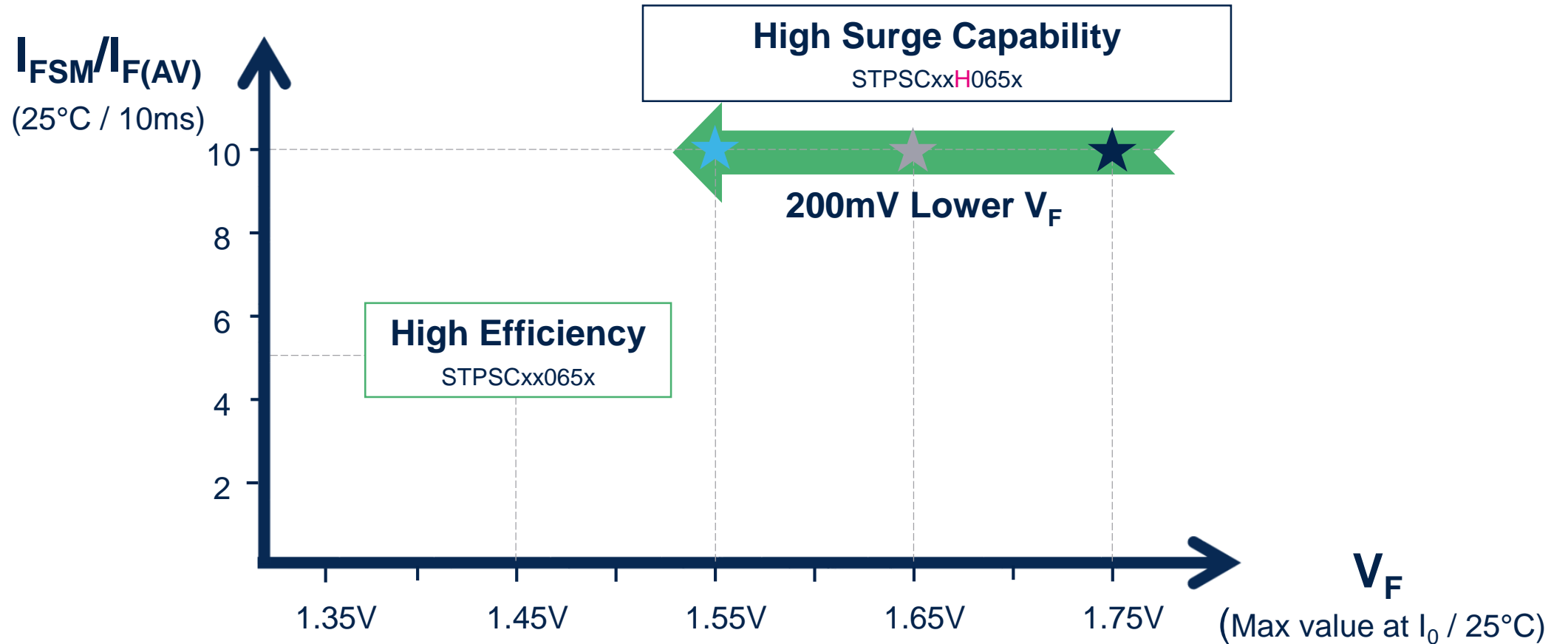


ST SiC diodes and feature





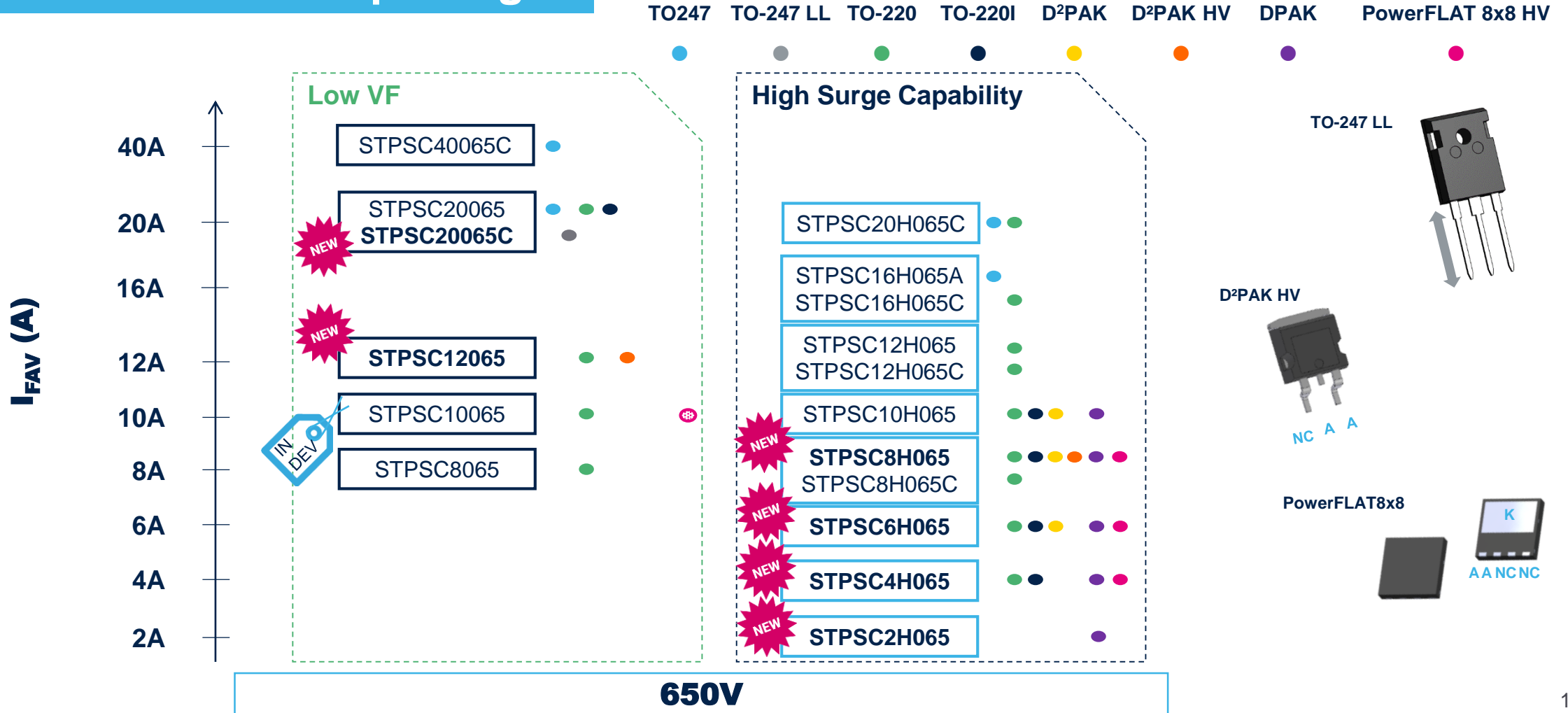
650V SiC Diodes product portfolio





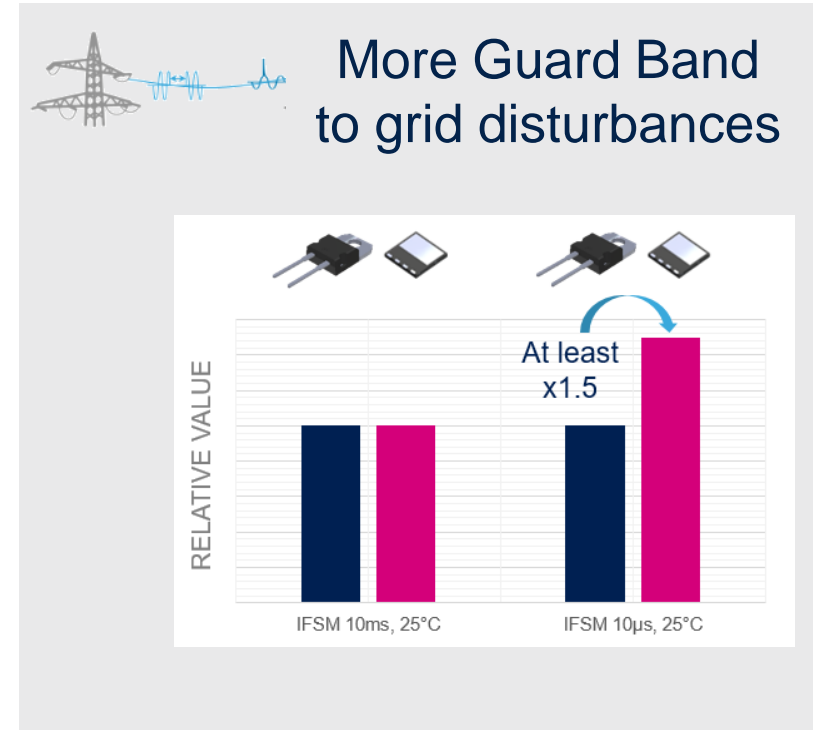
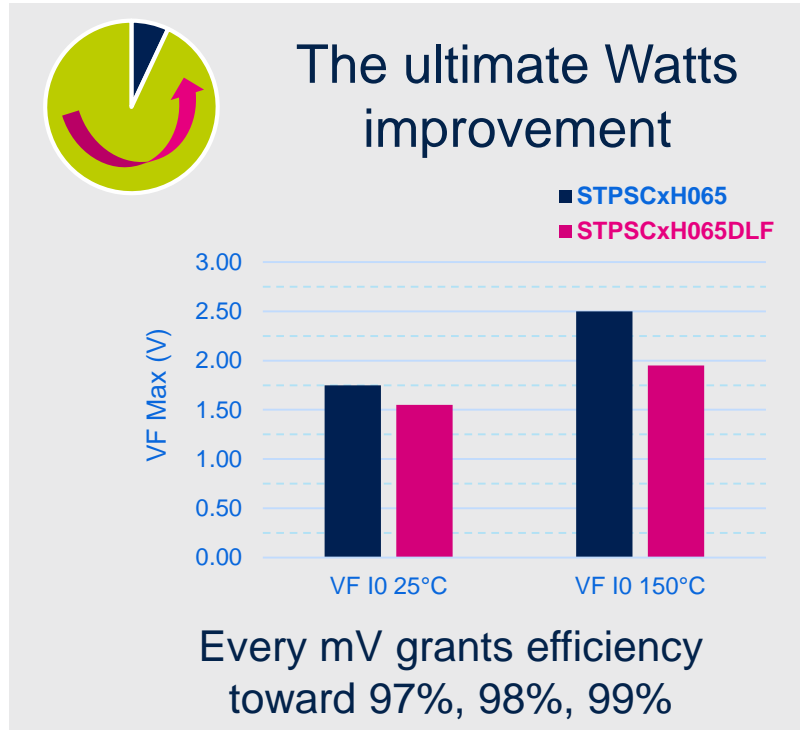
650V SiC Diodes product portfolio latest releases

SiC Diodes in new packages

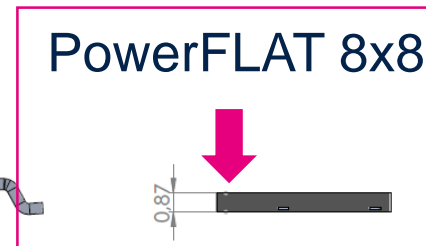
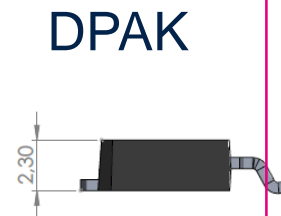
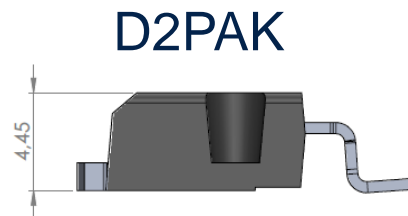


New PowerFLAT 8x8 package

... inside a less-than-1-mm thick package



&





New PowerFLAT 8x8 package

An improved Creepage Design

HIGH CREEPAGE

DPAK	<p>2.68mm 1.36mm 1.80mm</p>	PowerFLAT™ 8x8 HV	<p>2.75mm 2.60mm</p>	<p>Greater Package and Footprint Creepage than DPAK</p>
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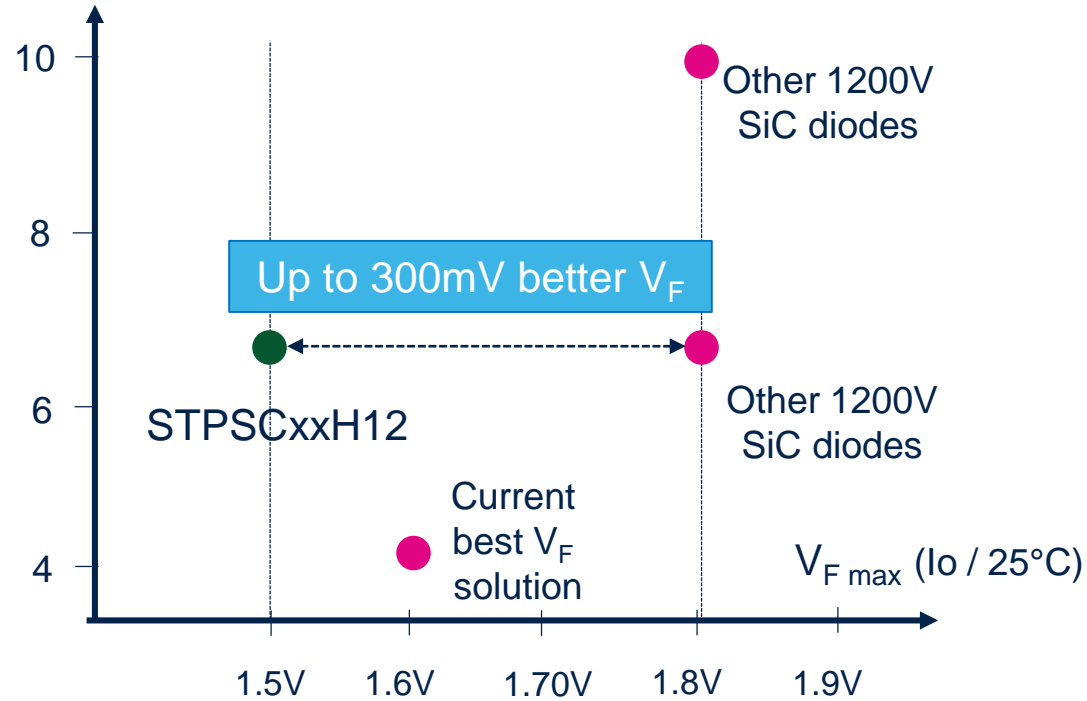
EASY COMPLIANCE TO IEC-60664-1*



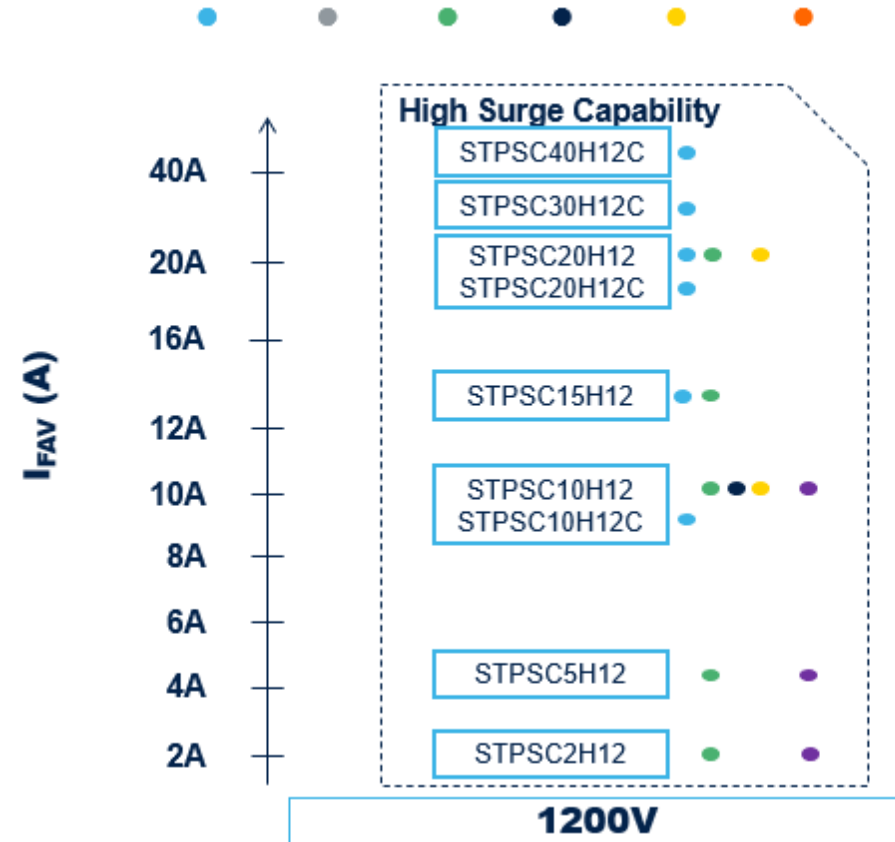
STPOWER SiC 1200V Diode

Benchmark on VF

$I_{FSM} / I_{F(AV)}$
(25°C / 10ms)

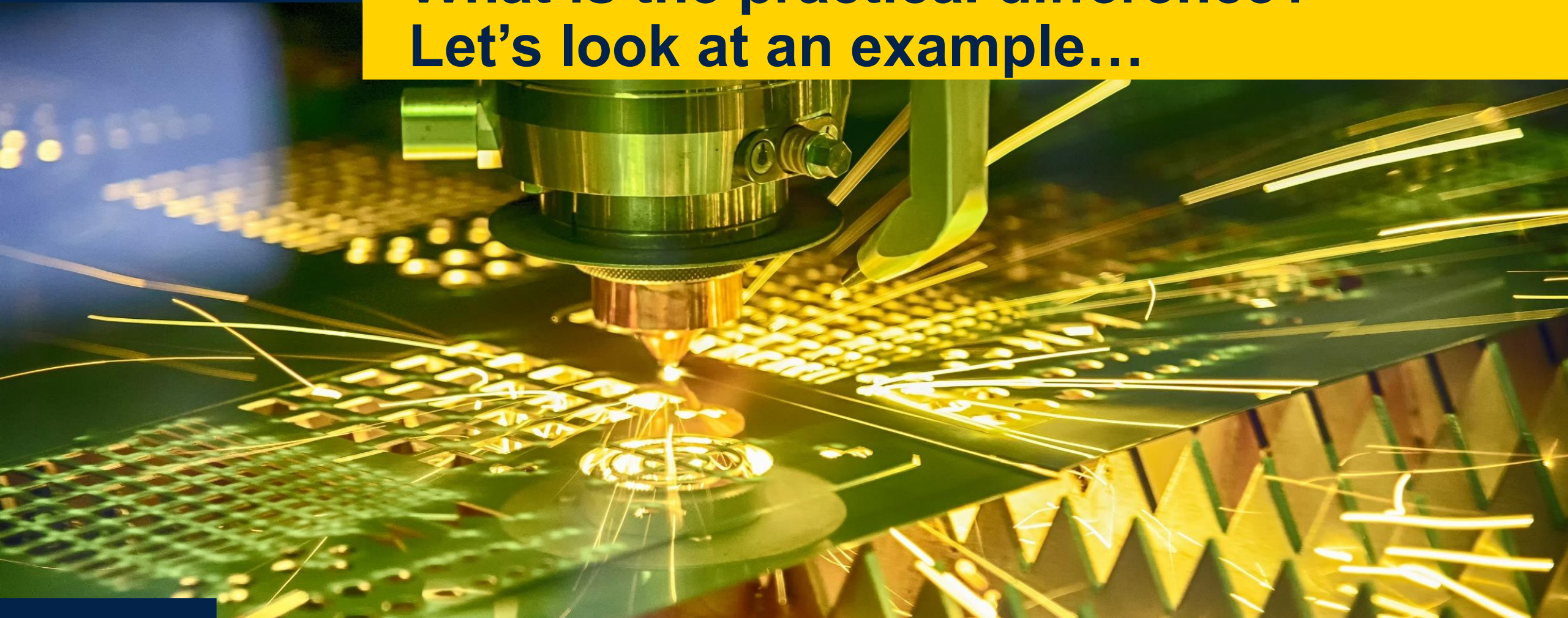


TO247 TO-247 LL TO-220 TO-220I D²PAK D²PAK HV DPAK

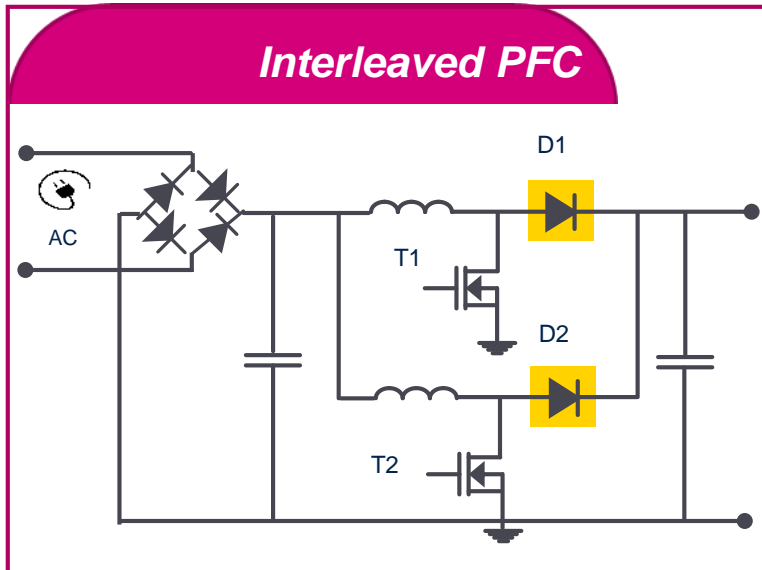


ST new SiC 1200V diode: the market reference on V_F

**Reverse recovery -
What is the practical difference?
Let's look at an example...**



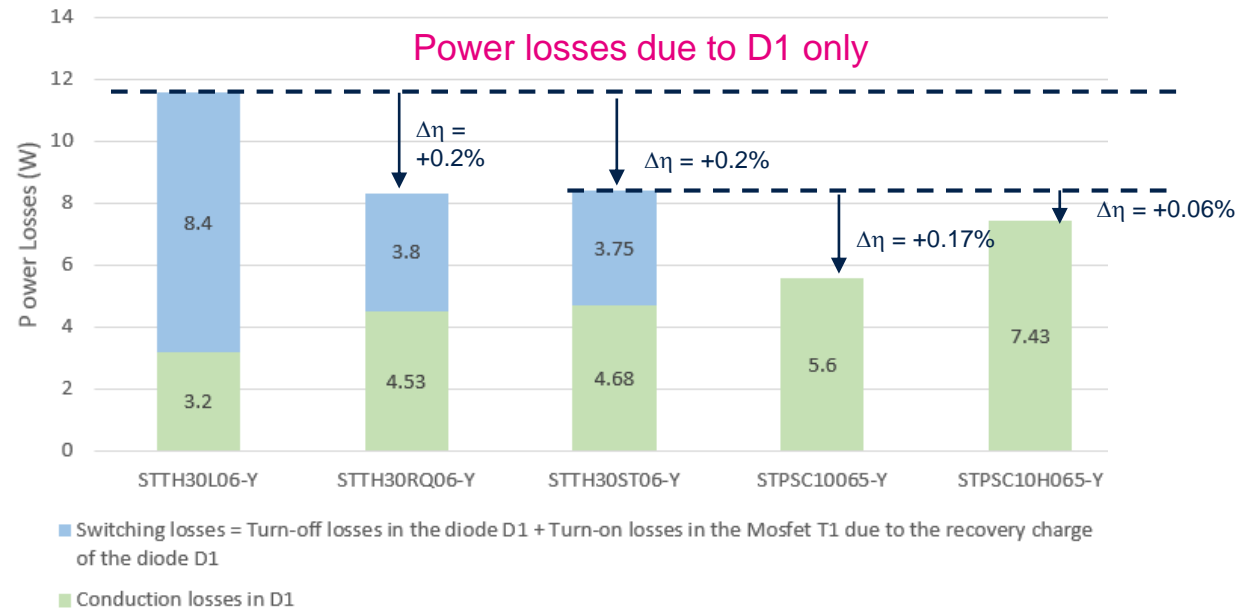
650V SiC Diode performances vs. Si Diode technology



Interleaved PFC 3.3kW: Power losses sharing

INTERLEAVED PFC 3.3kW (each PFC = 1.65kW)

Conditions: $V_{in} = 220V$, $F = 70kHz$, $T_j = 125^\circ C$, $dI/dt = 500A/\mu s$, $V_{PFC} = 400V$



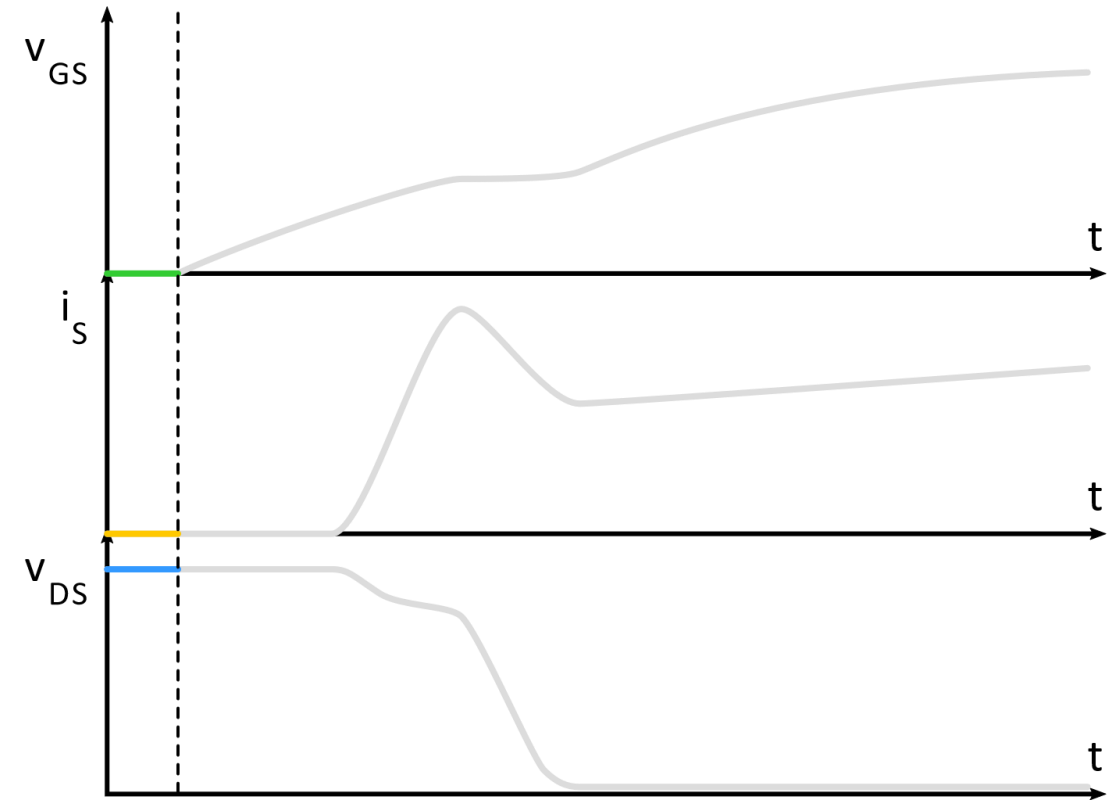
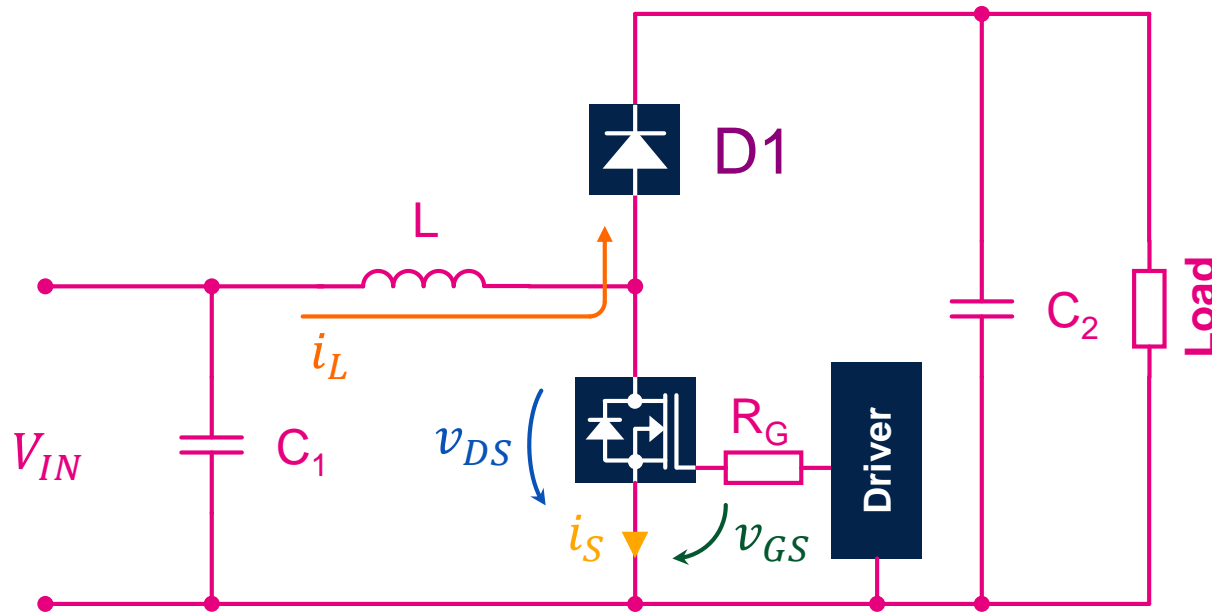
With SiC, we get :

- Best switching performance (fast and soft)
- Best efficiency in hard-switching applications thanks to best turn-off performance

Hard switching

Example: Boost in CCM, #1

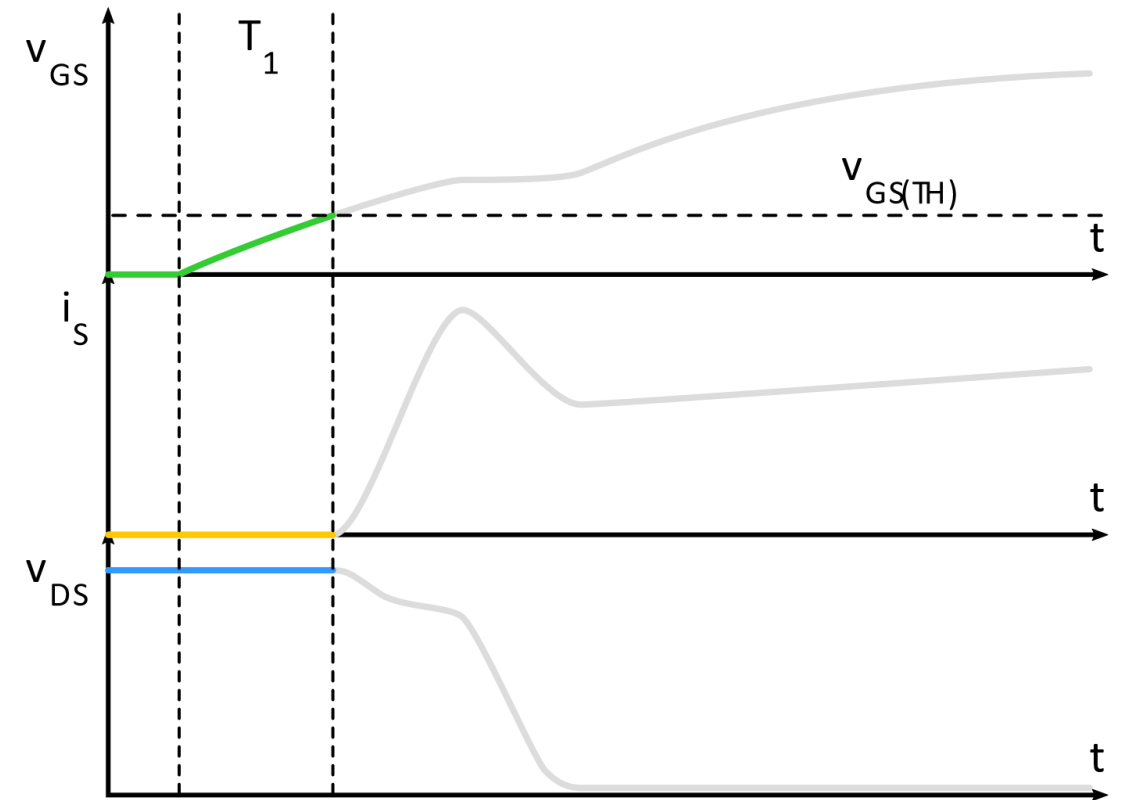
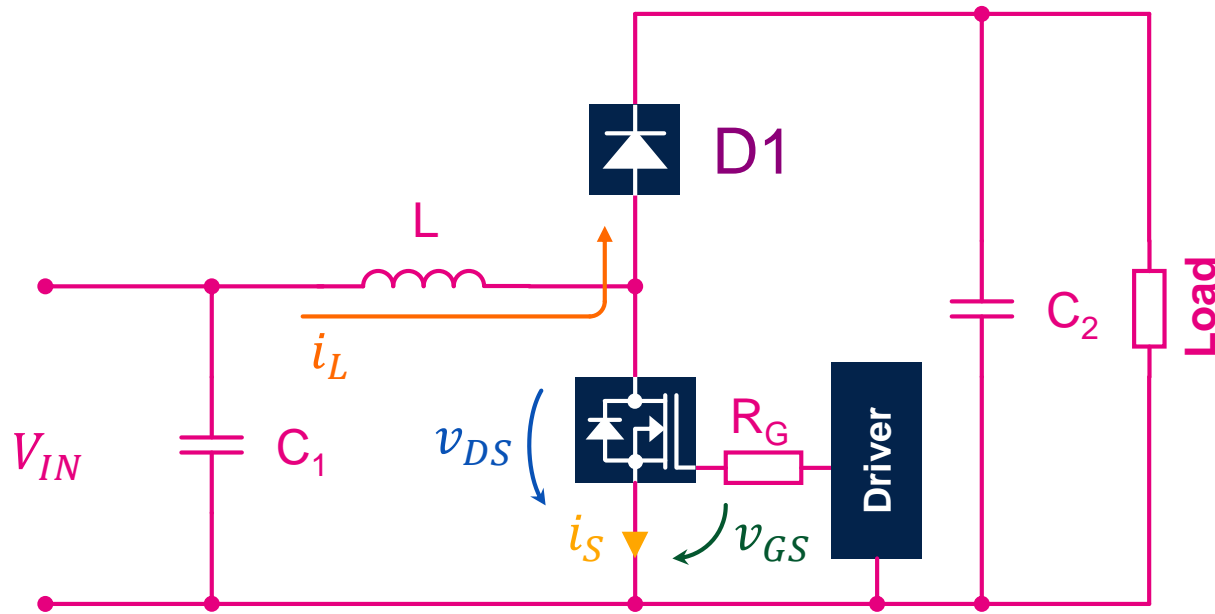
- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage



Hard switching

Example: Boost in CCM, #2

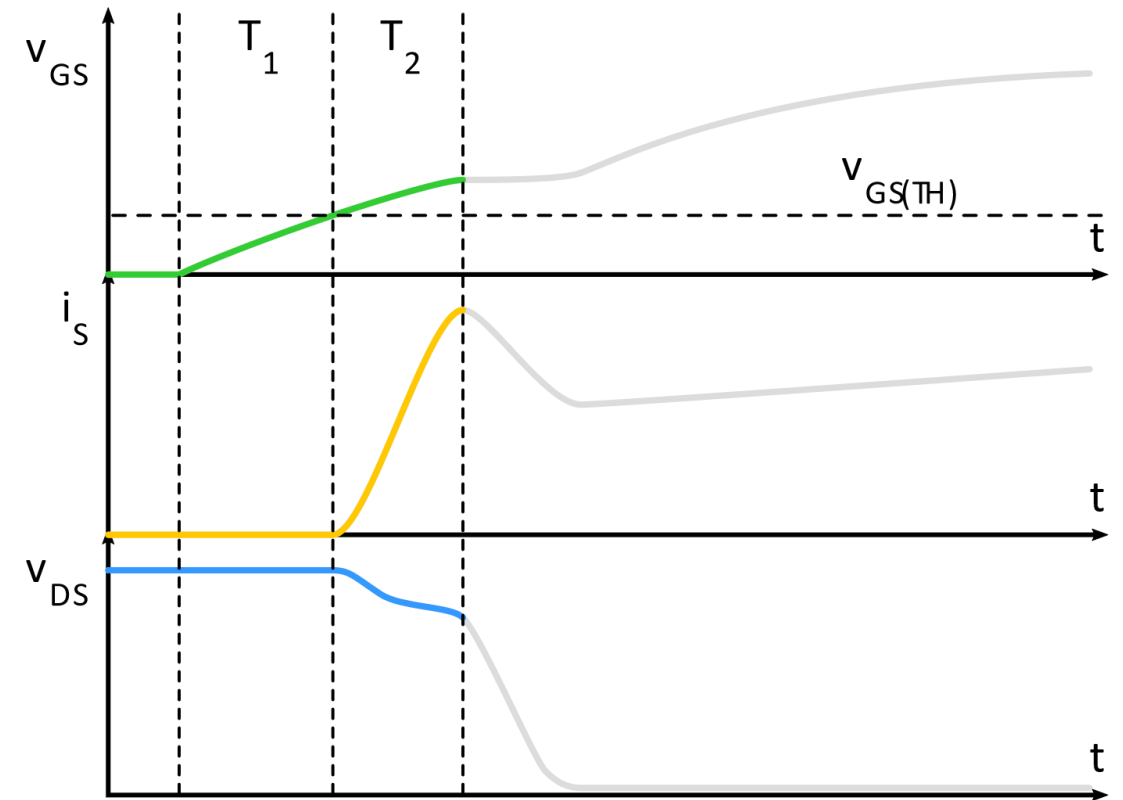
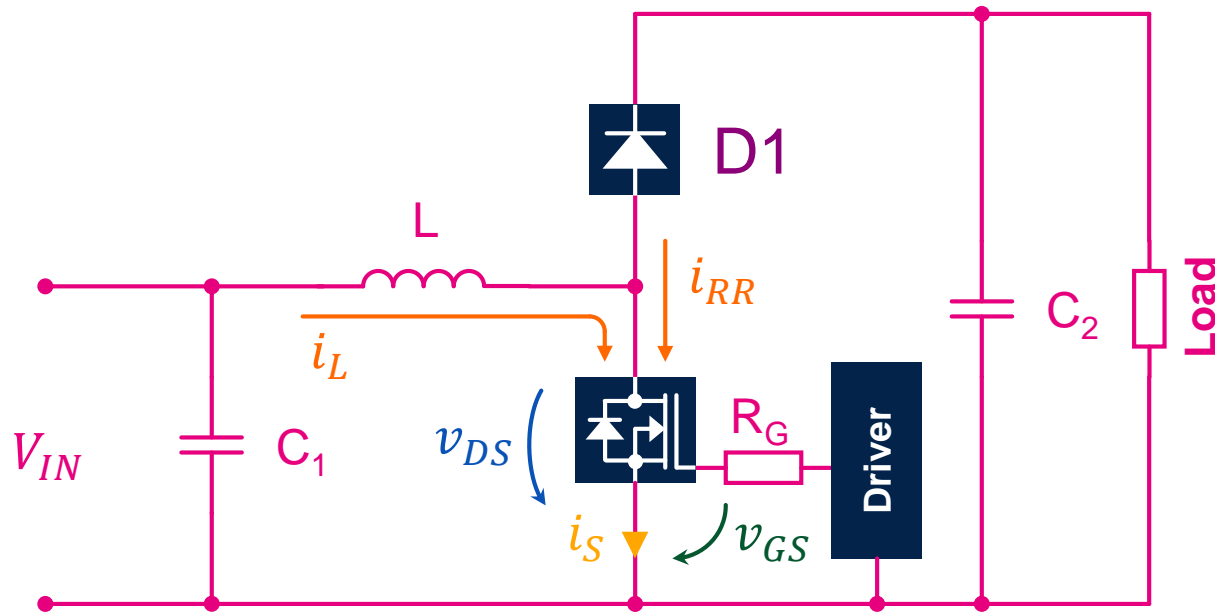
- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage



Hard switching

Example: Boost in CCM, #3

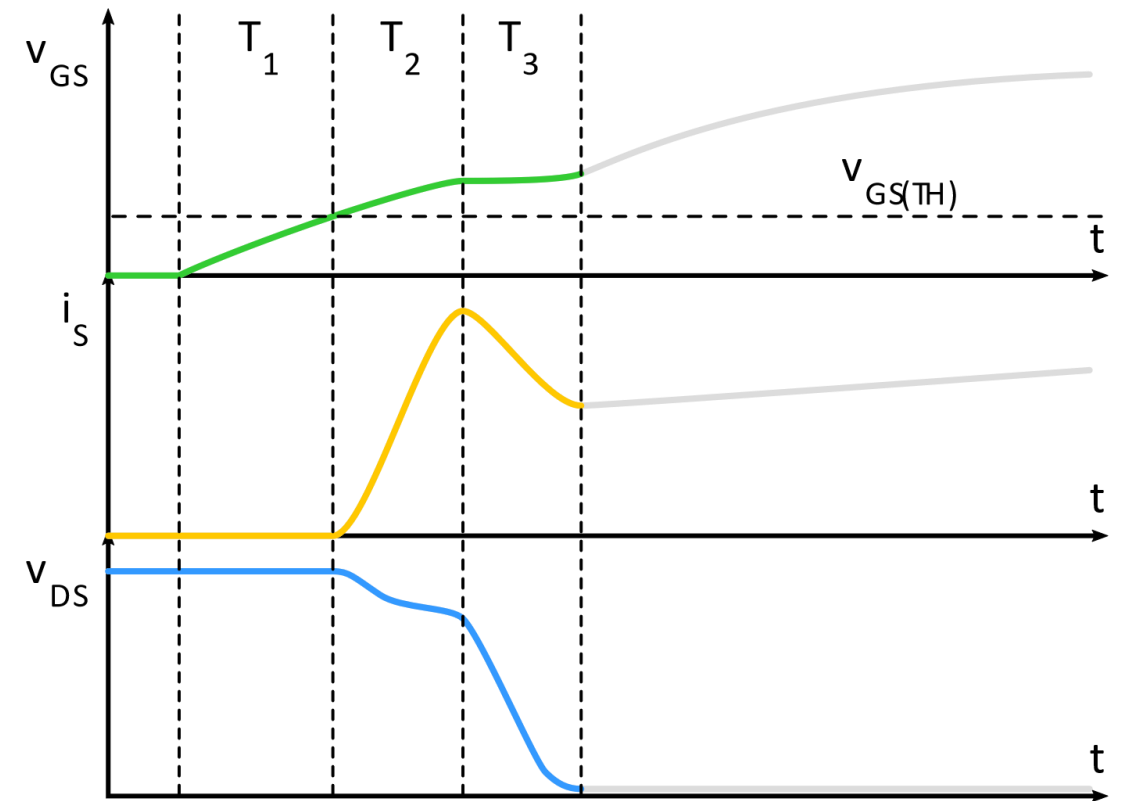
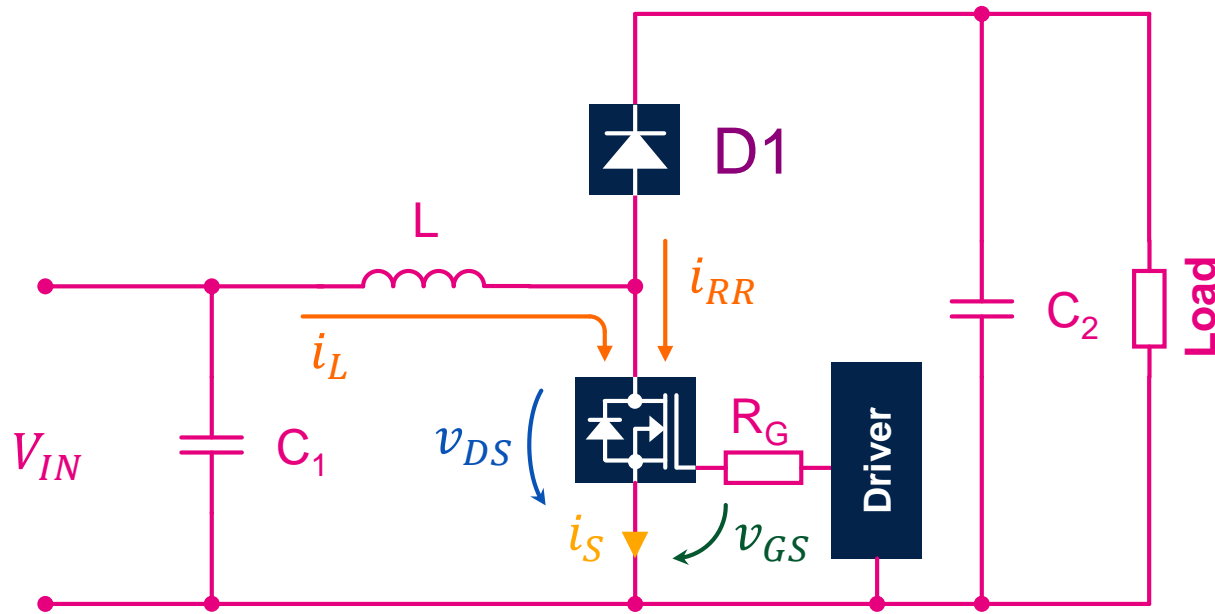
- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage



Hard switching

Example: Boost in CCM, #4

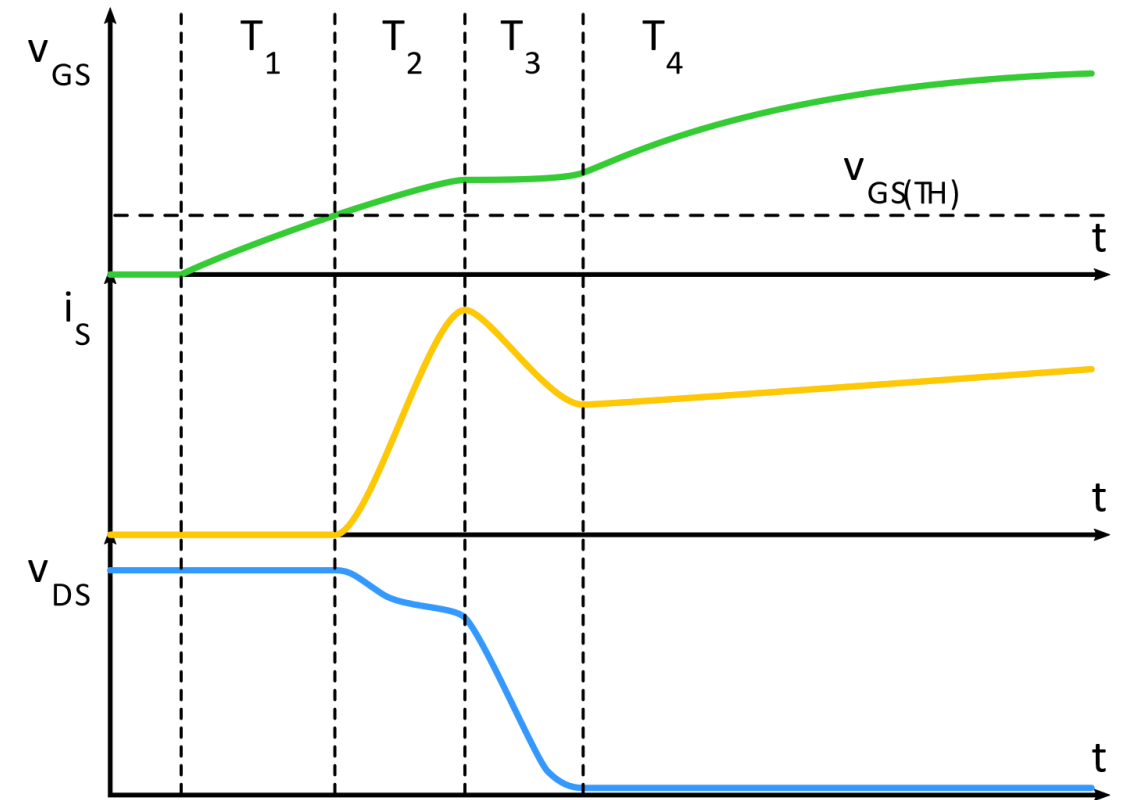
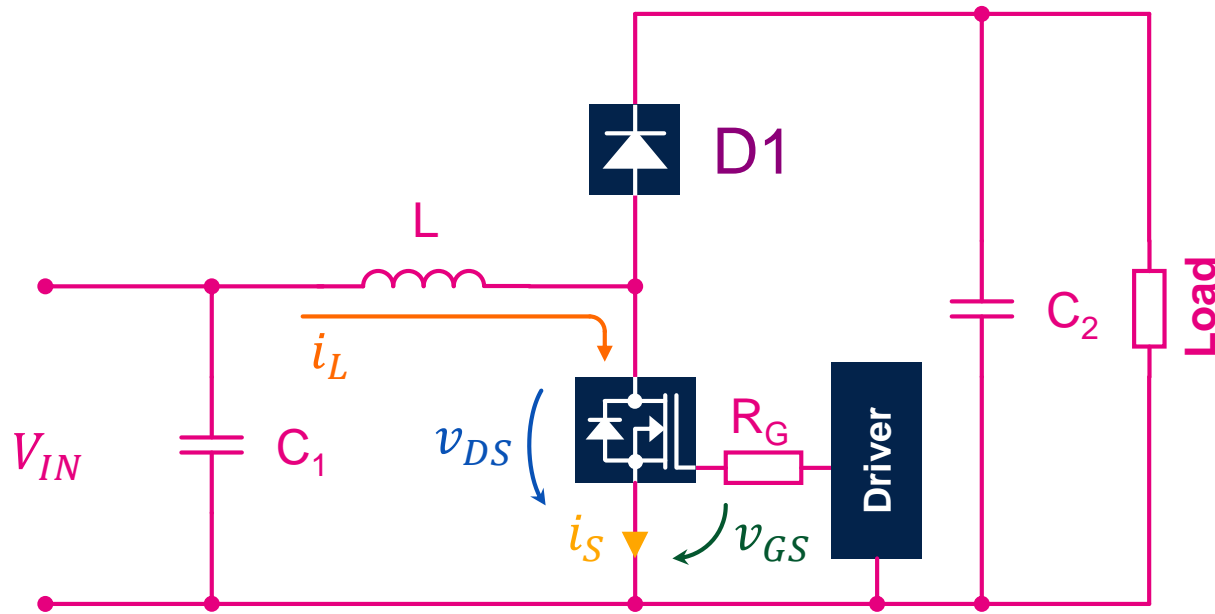
- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage



Hard switching

Example: Boost in CCM, #5

- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage



Hard switching

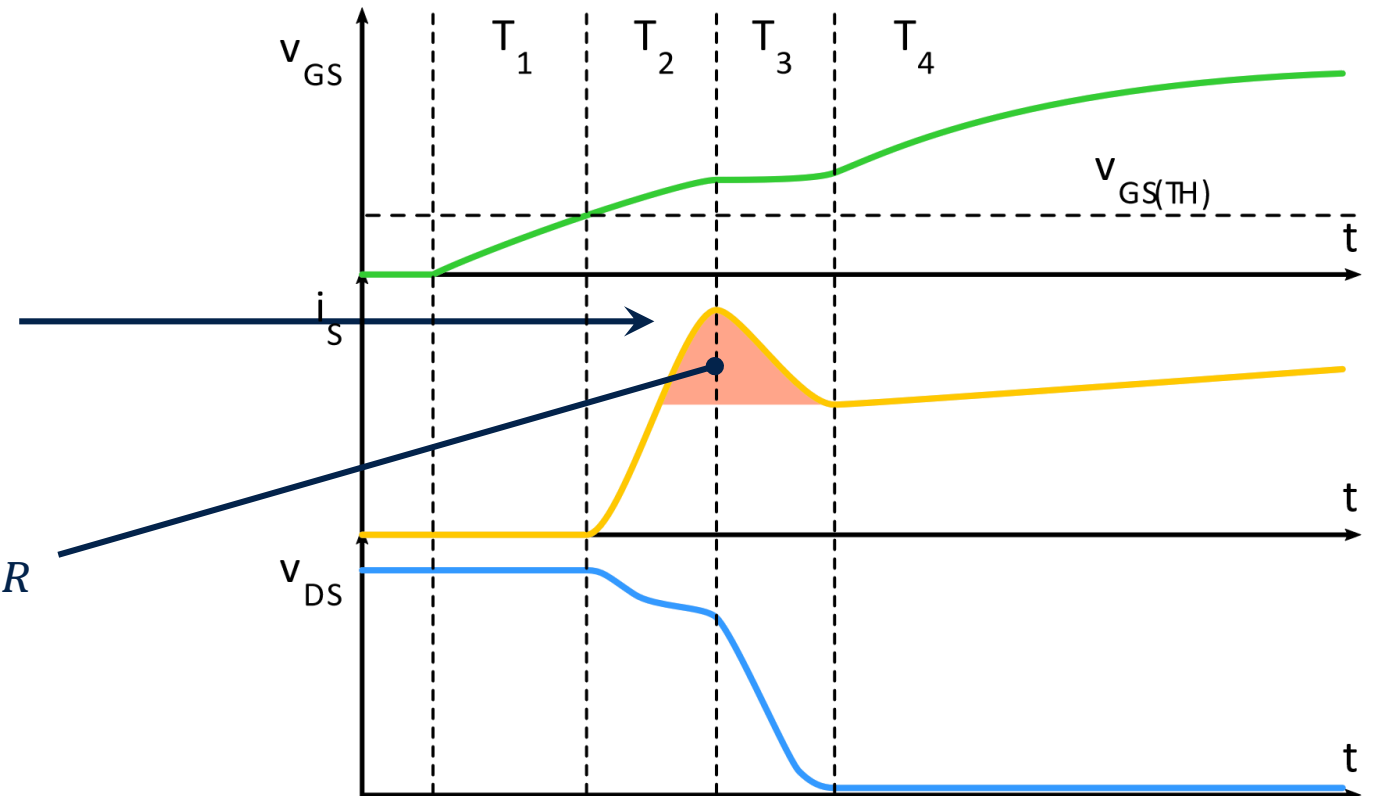
Example: Boost in CCM, #6

- Drain current driven by V_{GS}
- MOSFET channel starts conducting at full V_{DS} voltage

Reverse recovery of the boost diode D1

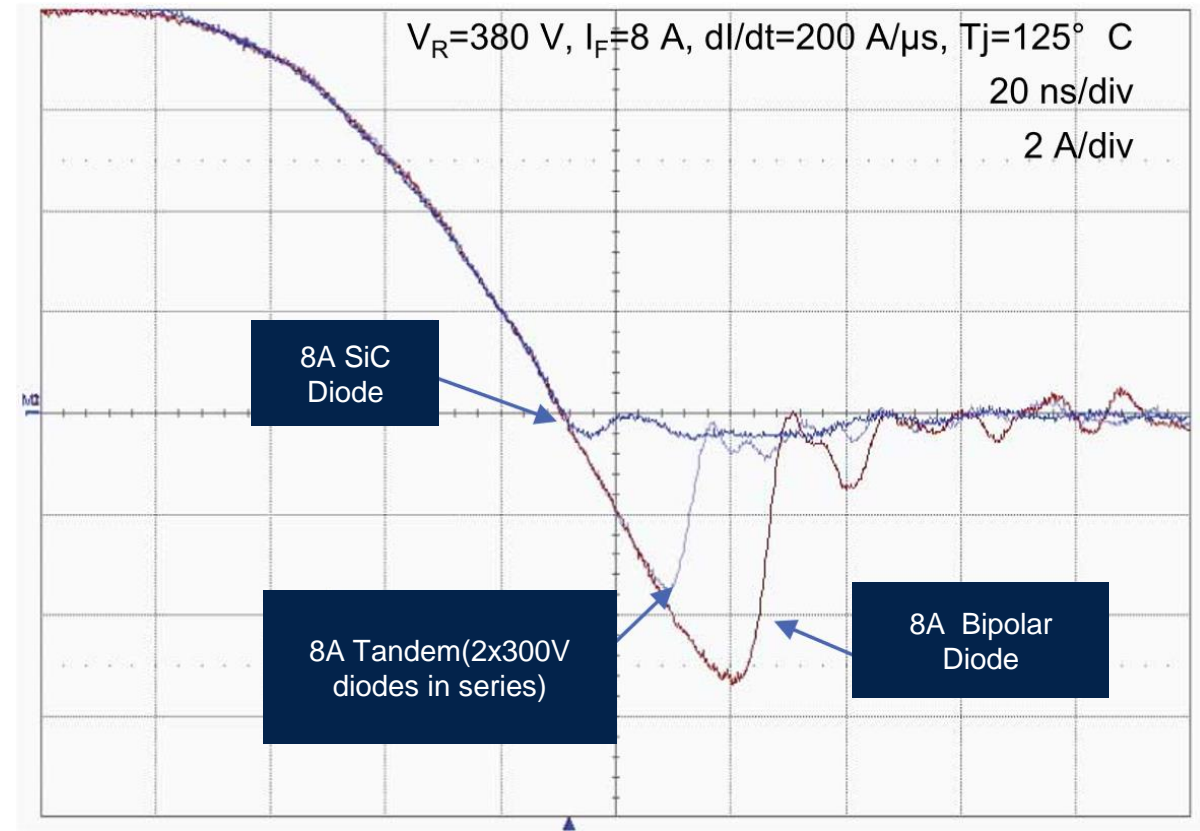
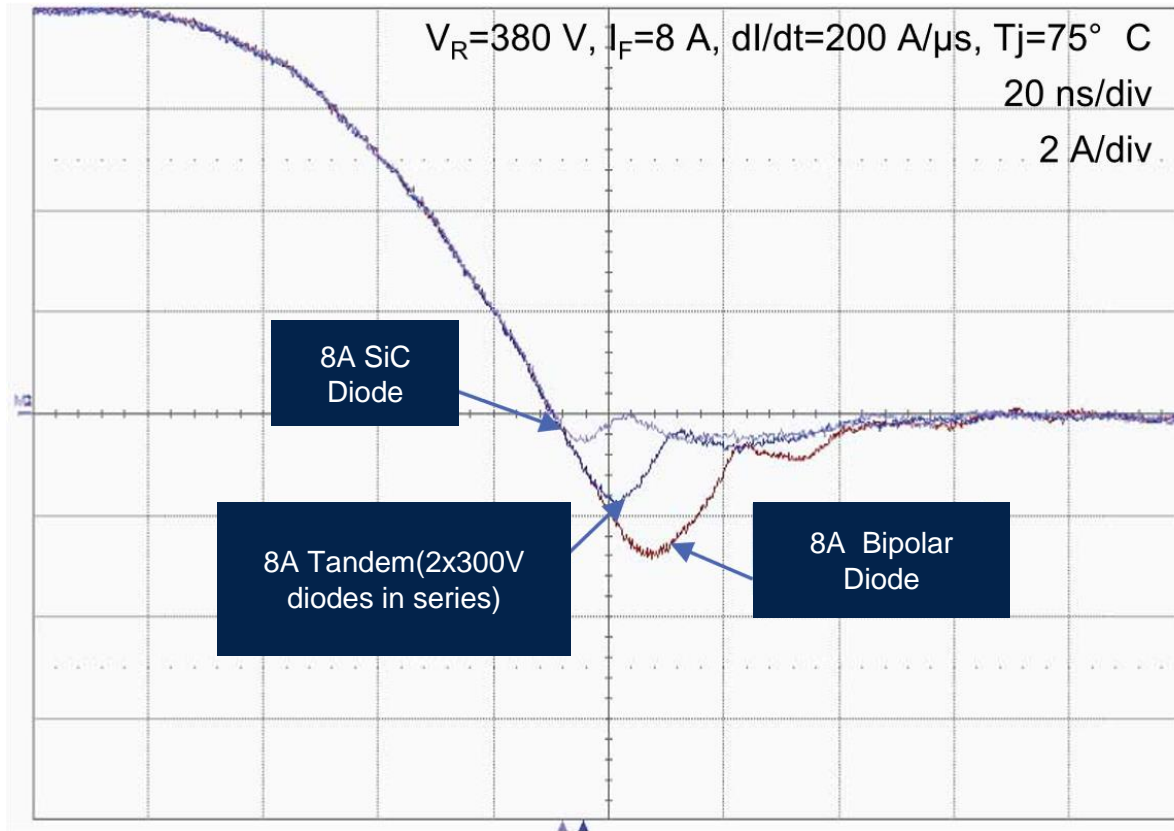
Area $\sim Q_{RR}$

- Q_{RR} dissipated in the MOSFET



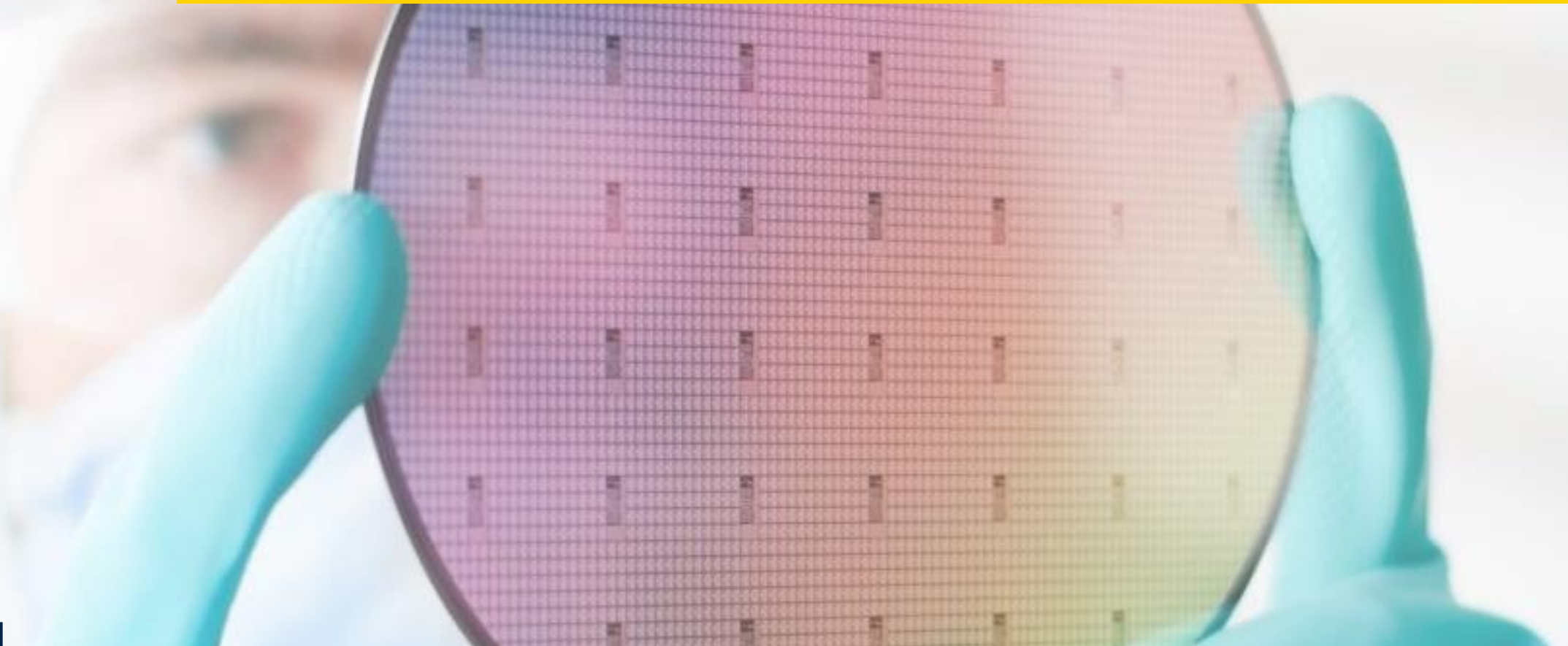
SiC diodes

Reverse recovery



- SiC boost diode D1 \Rightarrow no minority carrier recombination \Rightarrow no recovery
- Ideal for hard switching topologies

SiC MOSFET Products



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STPOWER SiC MOSFET series positioning

Breakdown Voltage

650V ★

1200V ★

1700V ★

Series

G2

G1

G2

G1

R_{DS(on)} mΩ

18-55

52-520

22-75

65-700

I_D Current

45-120A

12-65A

40-100A

6-25A

Focus Applications

Renewable energy
Power Supply
OBC, DC-DC

Power Conversion
Industrial drives



Photovoltaic
HVAC

Street Lighting
Charging stations
OBC, DC-DC, Traction

High Voltage
Power Supply
DC-DC



SiC MOSFET in Mass Production: 1200V Gen1 (1/3)

Part Number	V _{DS} [V]	R _{DS(on)} Typ @ 25 °C [Ω]	Id [A]	Package				
				HiP247	HiP247-LL	HiP247-4LL	H2PAK-2L	H2PAK-7L
<i>1200 Gen1 (Vgs=18V) series</i>								
SCT50N120	1200	0.052	65	x				
SCTWA50N120					x			
SCTWA50N120-4						x		
SCTH50N120-7								x
SCT30N120		0.080	40	x				
SCTWA30N120					x			
SCT30N120H							x	
SCT20N120		0.169	20	x				
SCTWA20N120					x			
SCT20N120H							x	
 SCT20N120AG					x			
SCT10N120					x			
SCTWA10N120	0.520	12		x				
SCT10N120H						x		
 SCT10N120AG				x				

 Automotive Grade

The Best Rdson vs. Tj behavior Option



SiC MOSFET in Mass Production: 650V Gen2 (2/3)

Part Number	V _{DS} [V]	R _{DS(on)} Typ @ 25 °C [Ω]	Id [A]	Package			
				HiP247	HiP247-LL	HiP247-4LL	H2PAK-7L
				T _{j max} = 200°C			T _{j max} = 175°C
<i>650 Gen2 (V_{gs}=18V) series</i>							
SCTW90N65G2V	650	0.018	119	x			
SCTWA90N65G2V					x		
SCTWA90N65G2V-4						x	
SCTH90N65G2V-7							x
SCTW100N65G2AG		0.020	100	x			
SCTWA100N65G2AG					x		
SCTWA100N65G24AG						x	
SCTH100N65G2-7AG							x
SCTW35N65G2V	650	0.55	45	x			
SCTWA35N65G2V					x		
SCTWA35N65G2V-4						x	
SCTH35N65G2V-7							x
SCTW35N65G2VAG				x			
SCTWA35N65G2VAG					x		
SCTWA35N65G2V4AG						x	
SCTH35N65G2V-7AG							x




Automotive Grade

The best Rdson vs Qg trade-off



SiC MOSFET in Mass Production: Gen2-1200V (3/3)

Part Number	V _{DS} [V]	R _{DS(on)} Typ @ 25 °C [Ω]	Id [A]	Package			
				HiP247	HiP247-LL	HiP247-4LL	H2PAK-7L
				<i>Tj max= 200°C</i>			
<i>1200 Gen2 (Vgs=18V) series</i>							
SCTW70N120G2V	1200	0.025	80	X			
SCTWA70N120G2V-4						X	
SCTH70N120G2V-7							X
SCTW40N120G2V		0.070	45	X			
SCTWA40N120G2					X		
SCTWA40N120G2V-4						X	
SCTH40N120G2V-7							X
 SCTW40N120G2VAG		0.075	35	X			
SCTWA40N120G2AG					X		
SCTWA40N120G24AG						X	
SCTH40N120G2V-7AG							X





Automotive Grade

1200V Gen2 -The Best Rdson vs. Qg trade off



SiC MOSFET Product Plan

1700V devices being introduced in mass production

Part Number	V _{DS} [V]	R _{DS(on)} Typ @ 25 °C [Ω]	Id [A]	Package				
				HiP247	HiP247-LL	HiP247-4LL	H2PAK-2L	H2PAK-7L
				T _{j max} = 200°C			T _{j max} = 175°C	
<i>1200 Gen2 (V_{gs}=18V) series</i>								
SCT1000N170	1700V	1	6	x				
 SCT1000N170AG				x				
SCTWA1000N170					x			
SCT20N170		0.064	25	x				
 SCT20N170AG				x				
SCTWA20N170					x			

 Automotive grade

1700V SiC MOSFET's – The First Very High Voltage devices Automotive & Industrial Qualified



SiC MOSFET: advanced packaging technologies

Package offer - Discrete – Bare Dice – Advanced packages

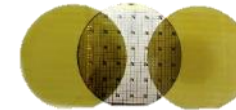
Key advantages to...

- Increase Power Density
- Reduce parasitic effects
- Target higher efficiency

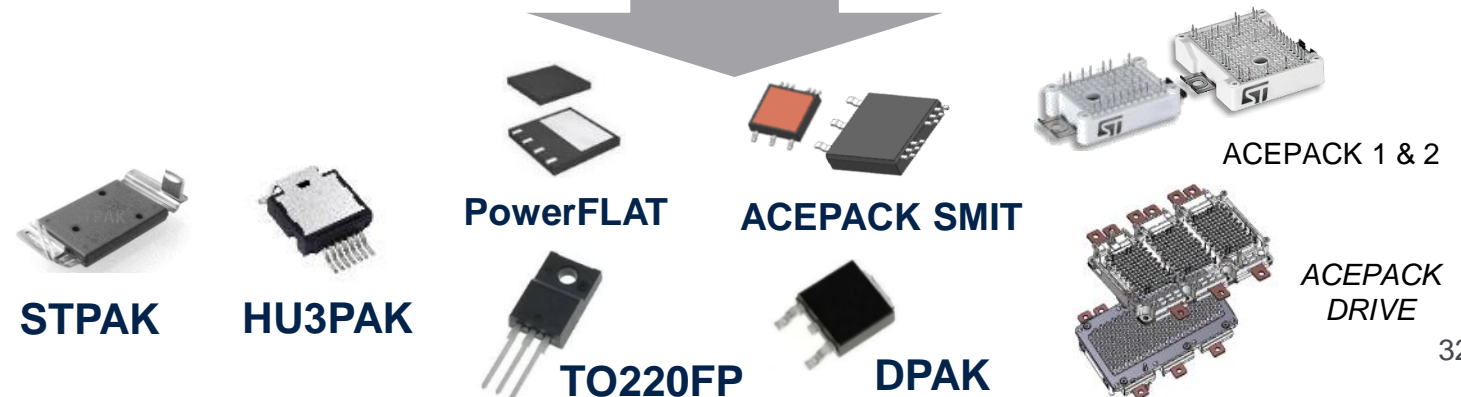
Available Packages



Bare Dice Strategic offer for Key Players



SiC Forthcoming Packages



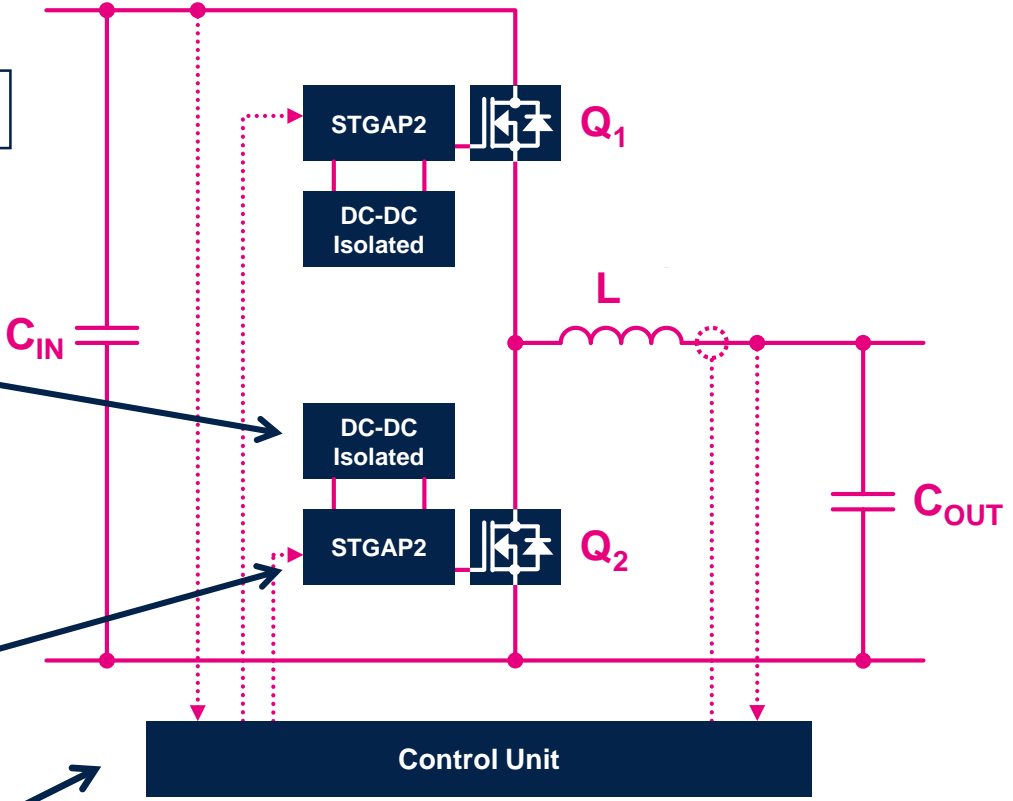
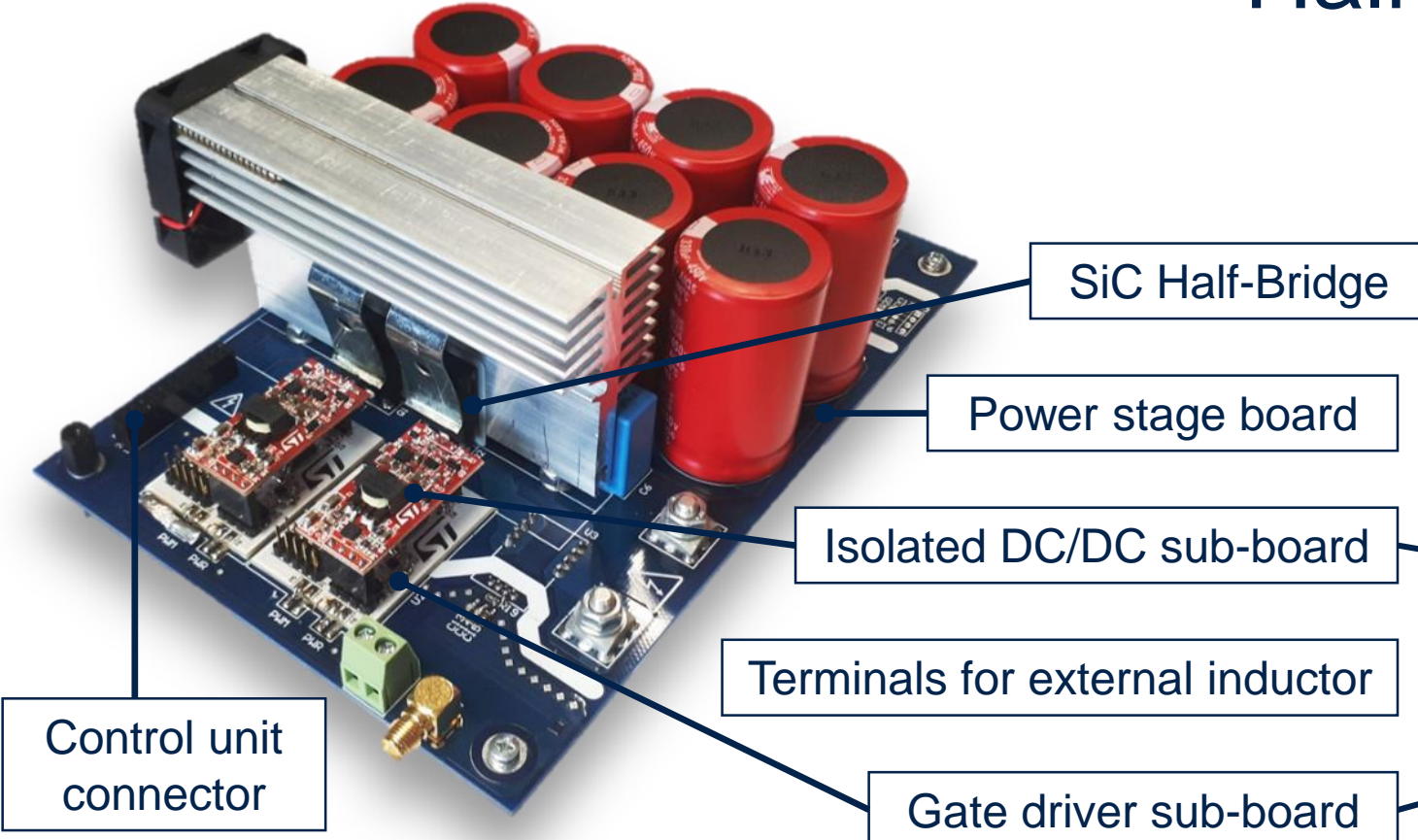
Rated at
200°C!!!



Switching performance measurement



Half-Bridge testing platform Buck / Boost



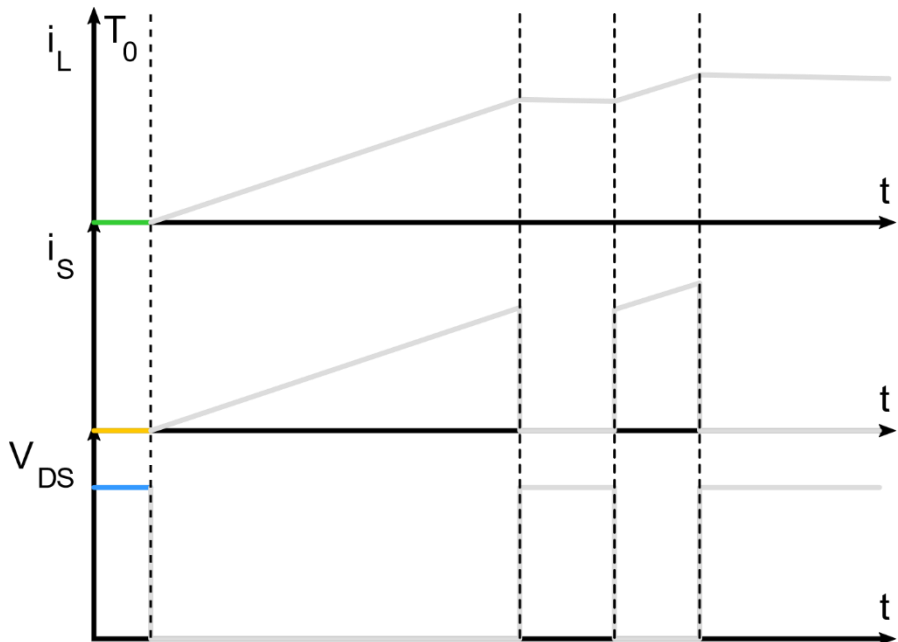
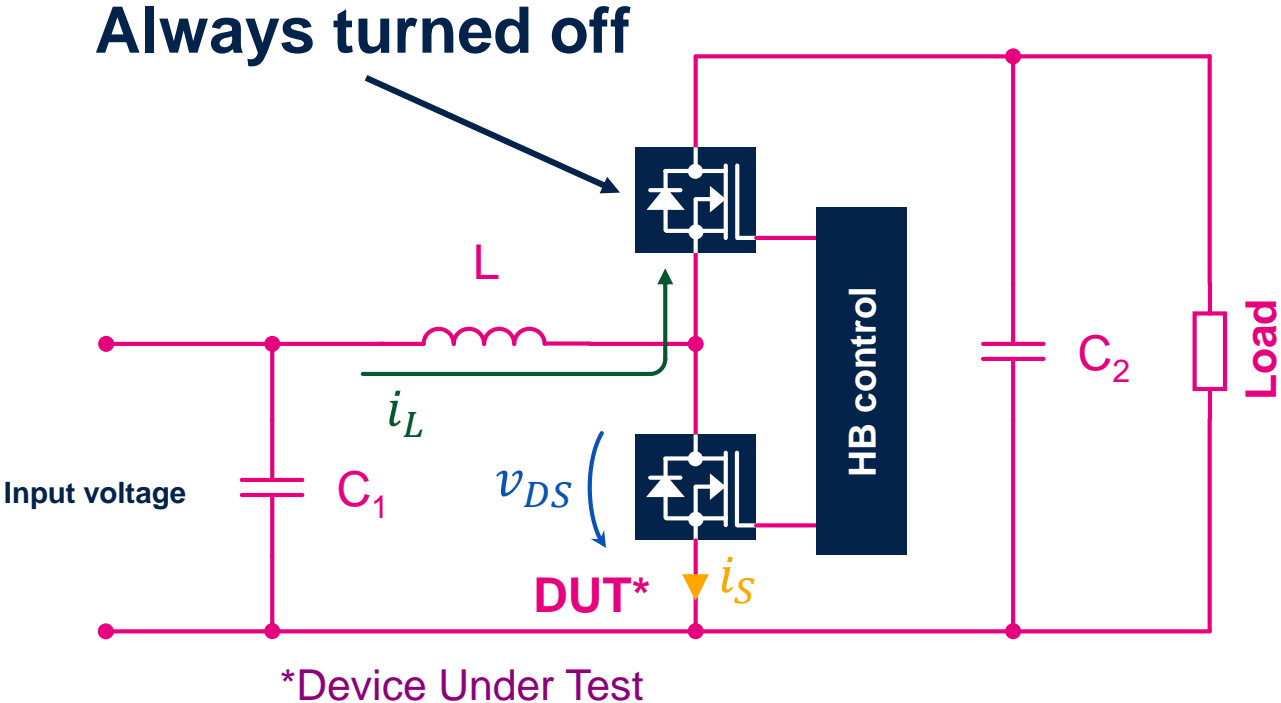
Control board based on STM32 MCU

Deliverables

- SiC MOSFET switching behavior, in combination with Switch/Diode
- Dynamic losses of power semiconductors
- Reference design for STGAP2
- Reference design for DC/DC converter

Double pulse test Principle of operation #1

T₀: Idle Stage

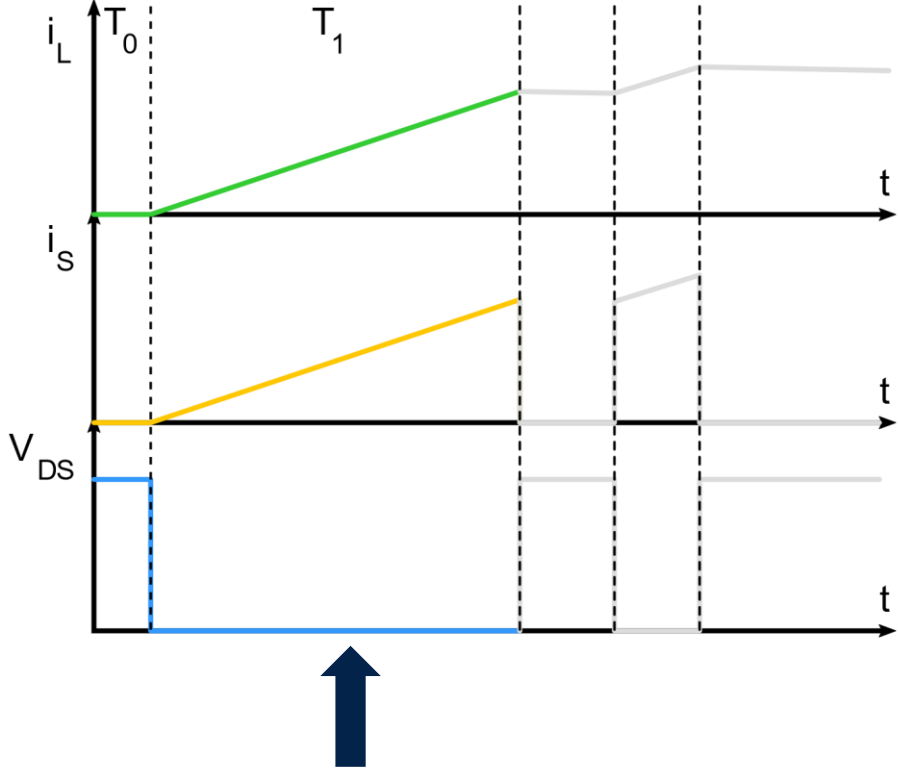
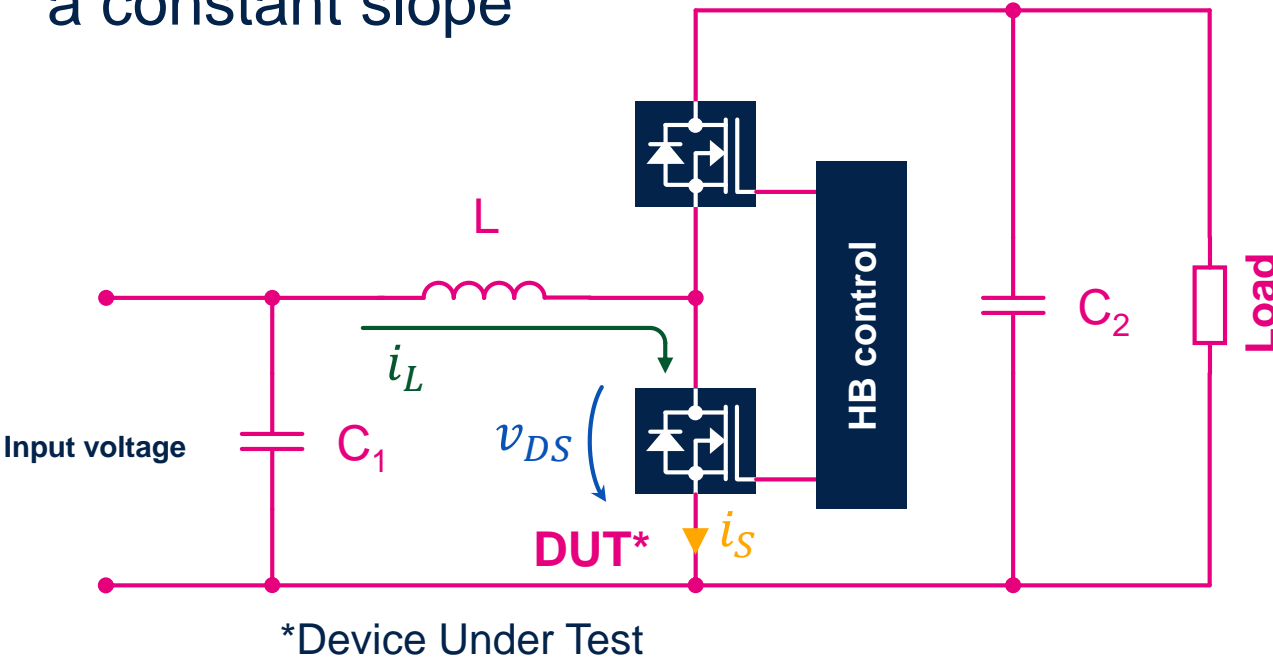


The Double-Pulse test is perfectly suited to measure the switching energy of a DUT (Device Under Test)

Double pulse test Principle of operation #2

T₁: Linear current Increase

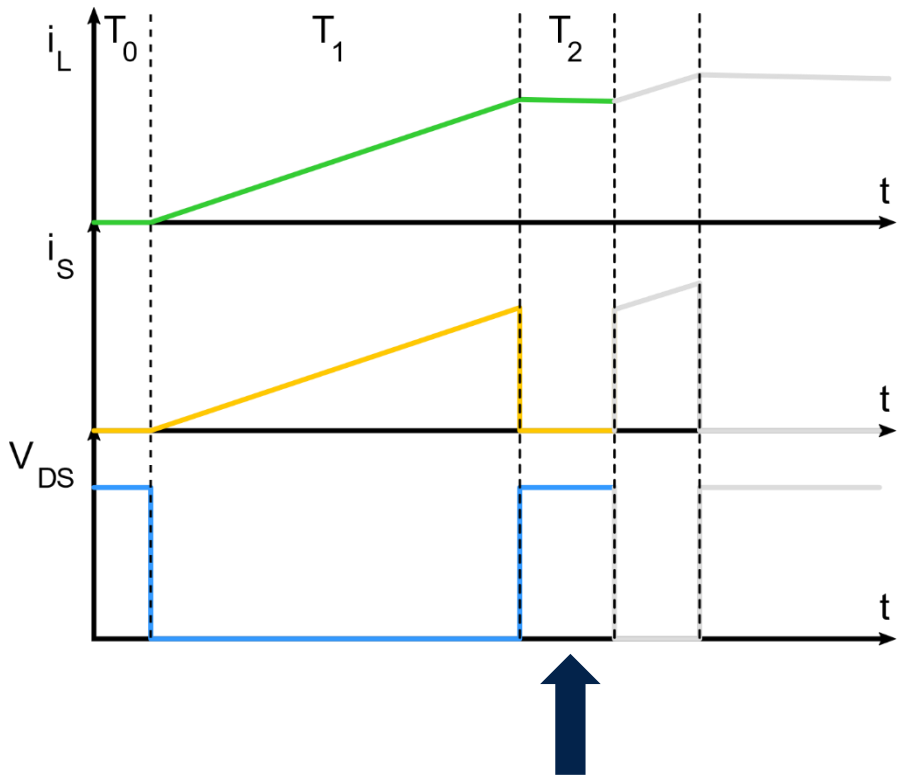
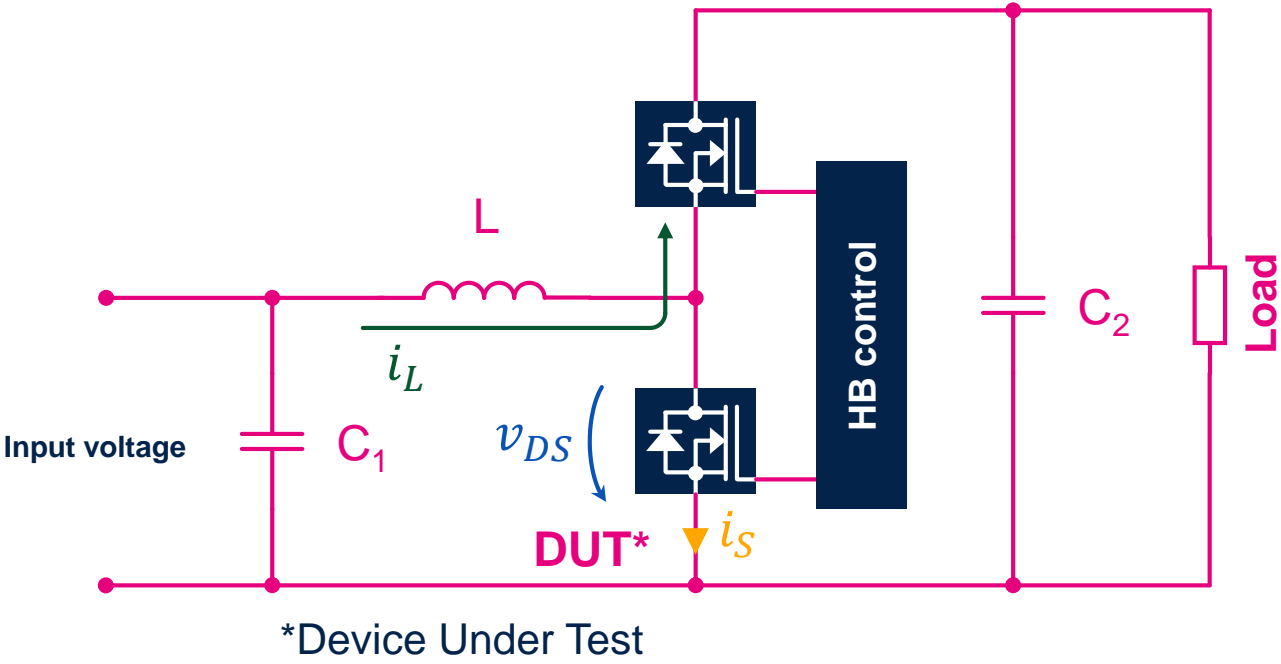
$\frac{di}{dt} = \frac{V_L}{L} \rightarrow$ current increases with a constant slope



T₁ long enough to reach the wished current level.

Double pulse test Principle of operation #3

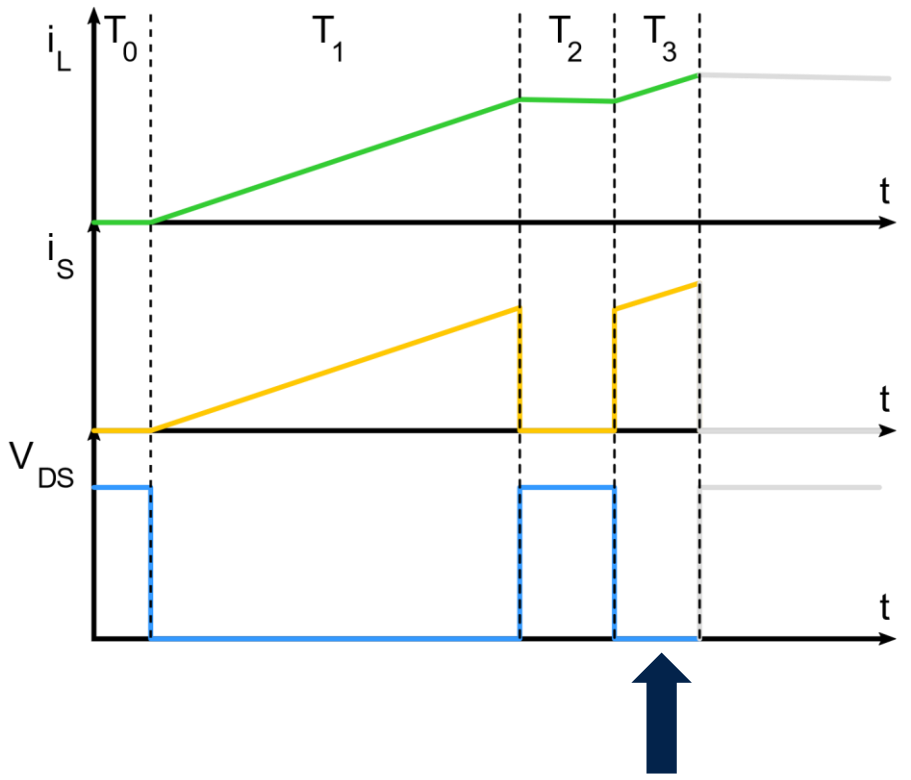
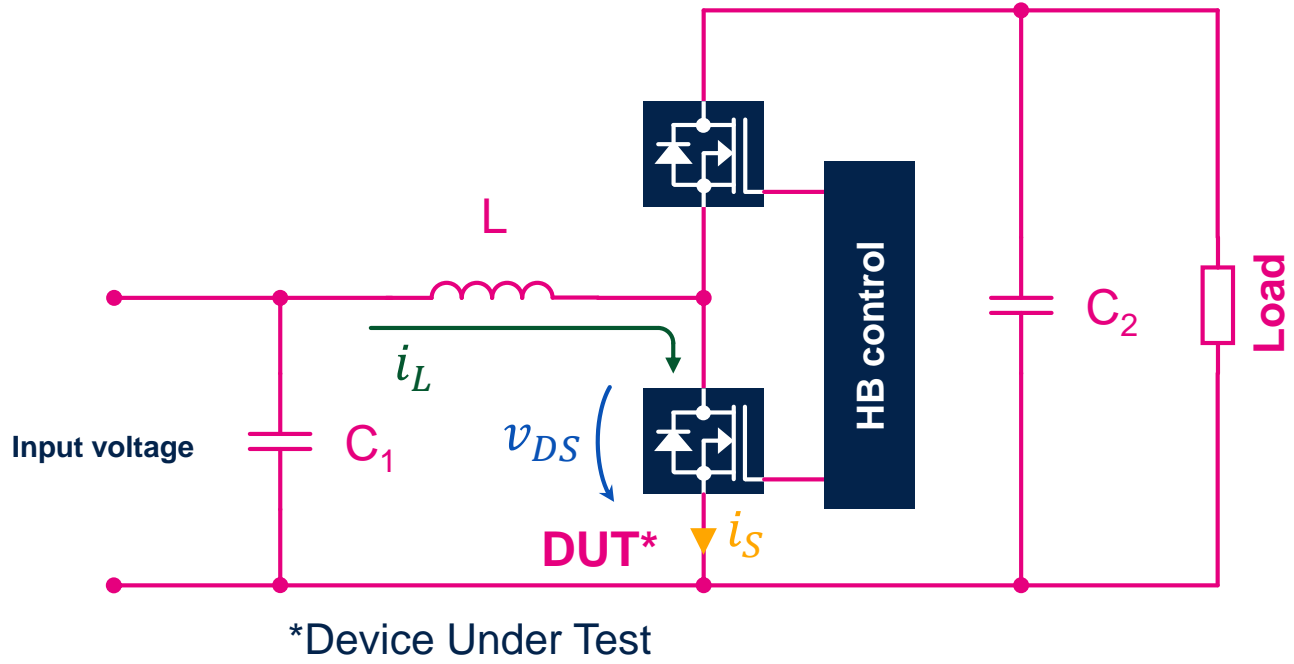
T₂: Free-Wheeling Phase



T₂ long enough to wait for switch-off transient, but not too long to decrease inductor current too much₃₇

Double pulse test Principle of operation #4

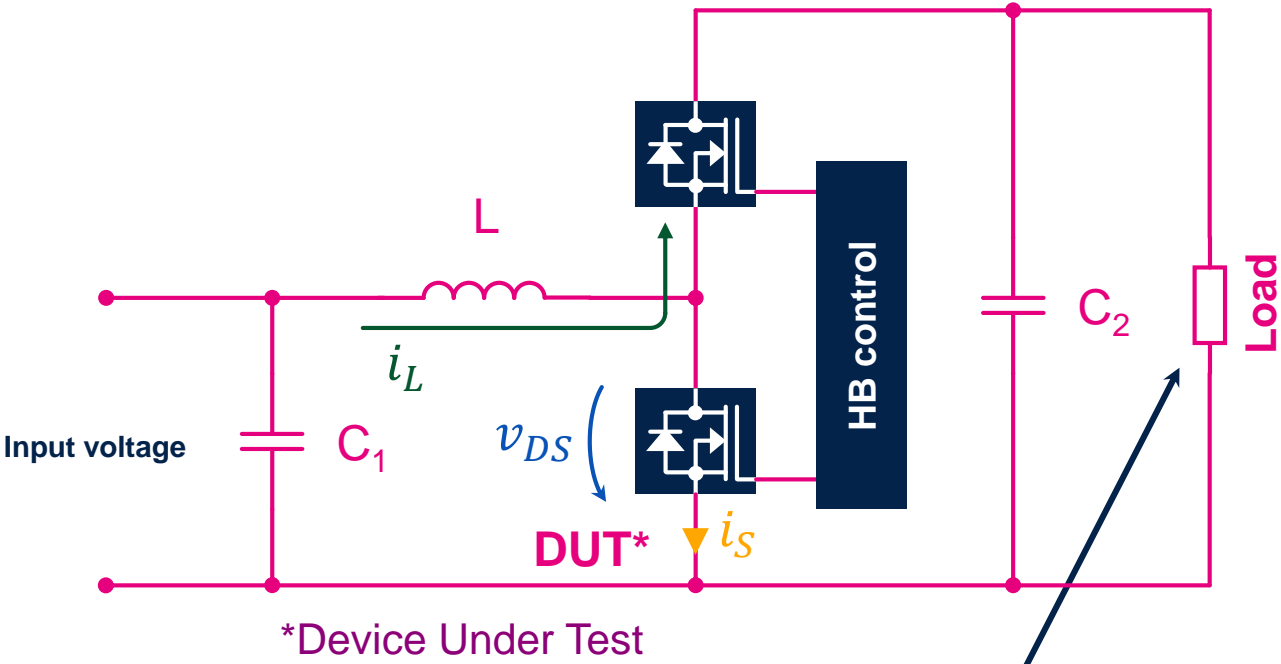
T_3 : 2nd Linear Increase Phase



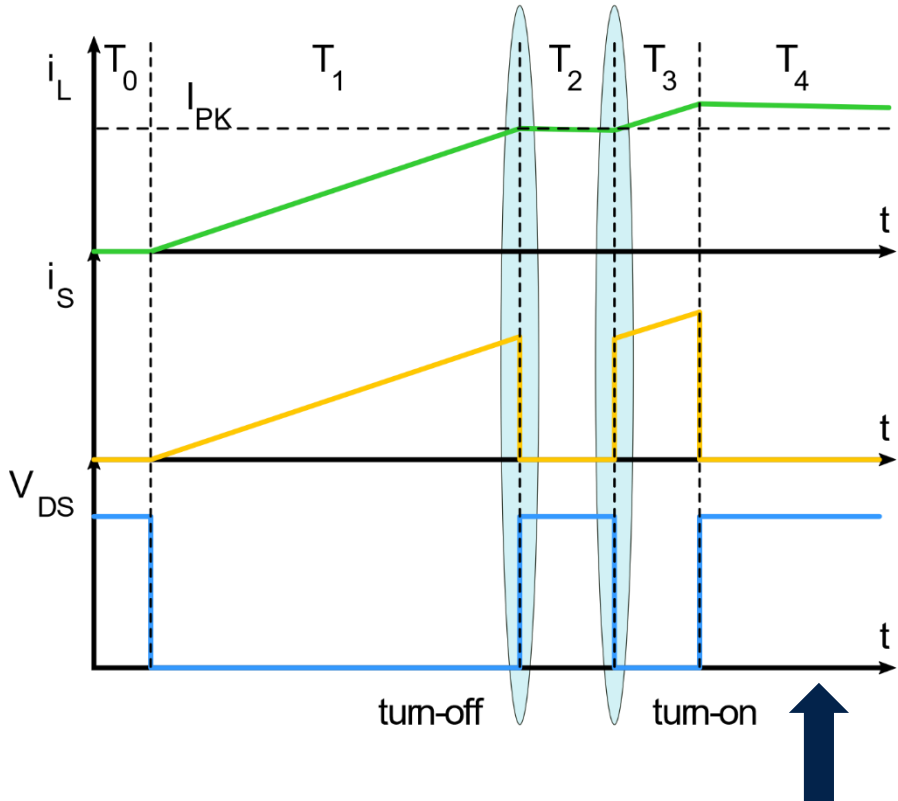
T_3 long enough to wait for
switch-on transient.

Double pulse test Principle of operation #5

T₄: Reset Phase



Sufficient load to dissipate energy from the inductor before the next period

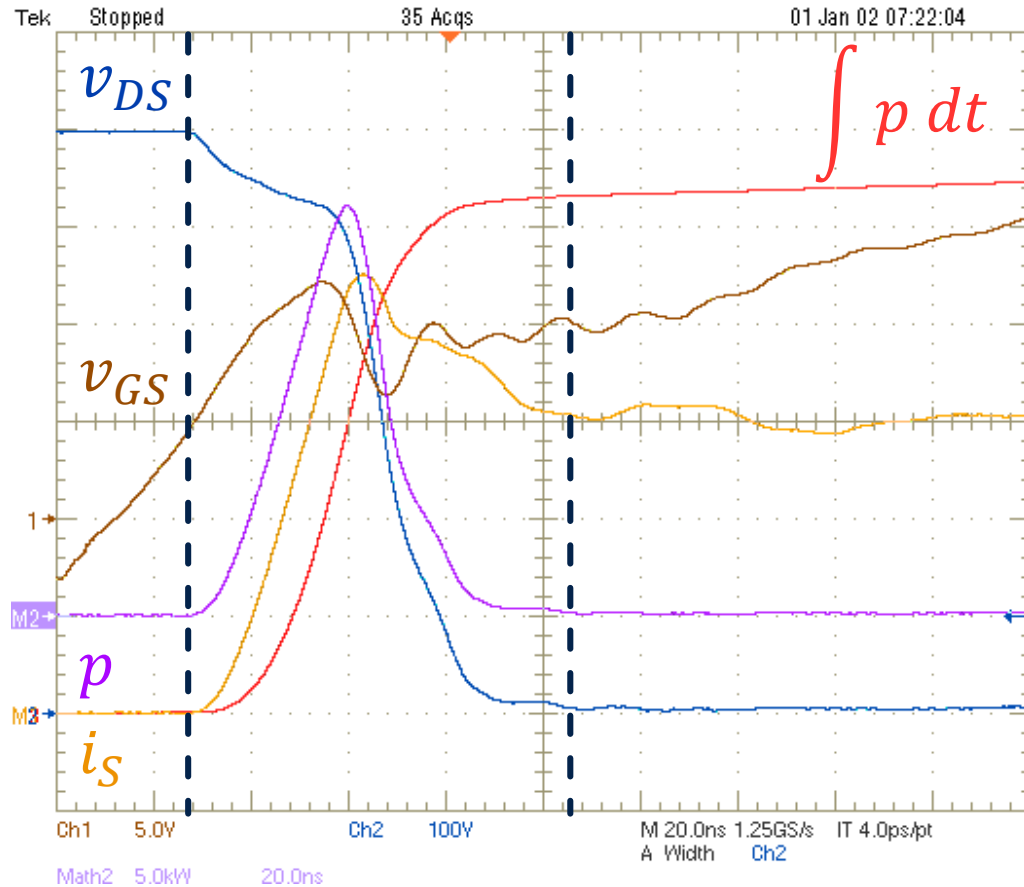


T₄ long enough to demagnetize the inductor.

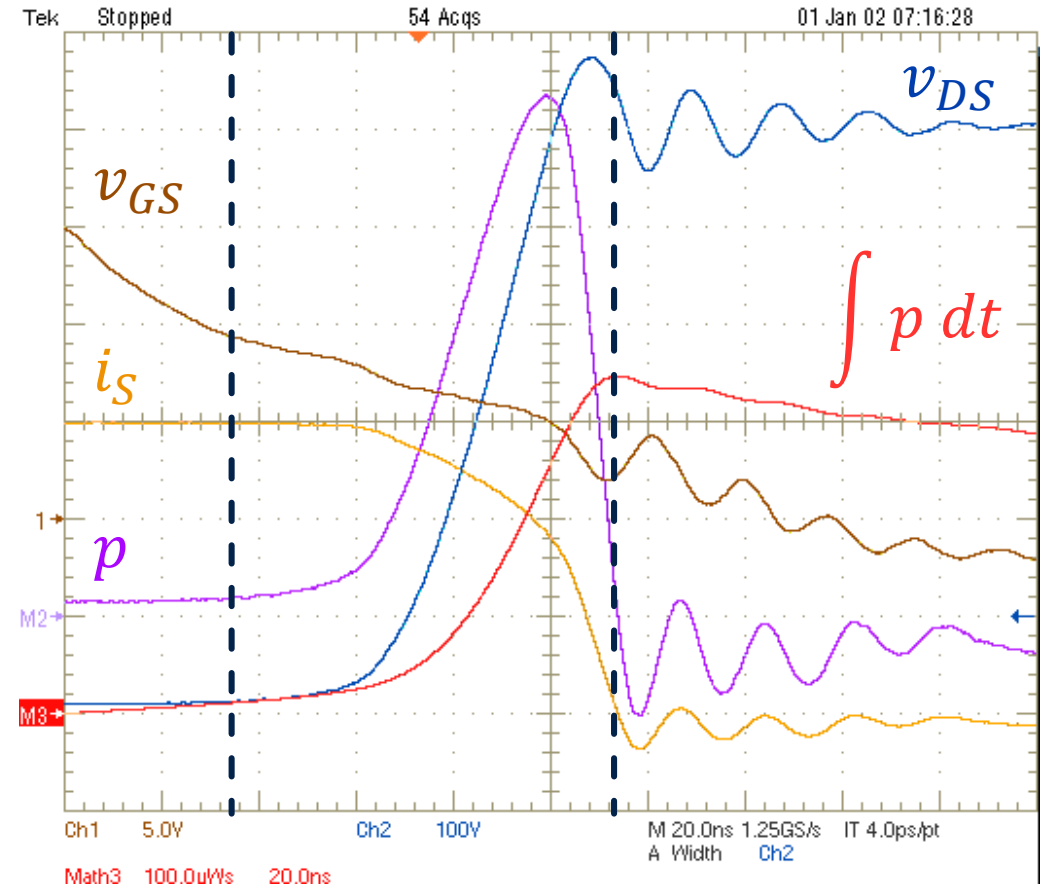
Switching energy measurement

Turn-on/off transient detail

$$R_G = 10 \Omega, I_{PK} = 30 A$$



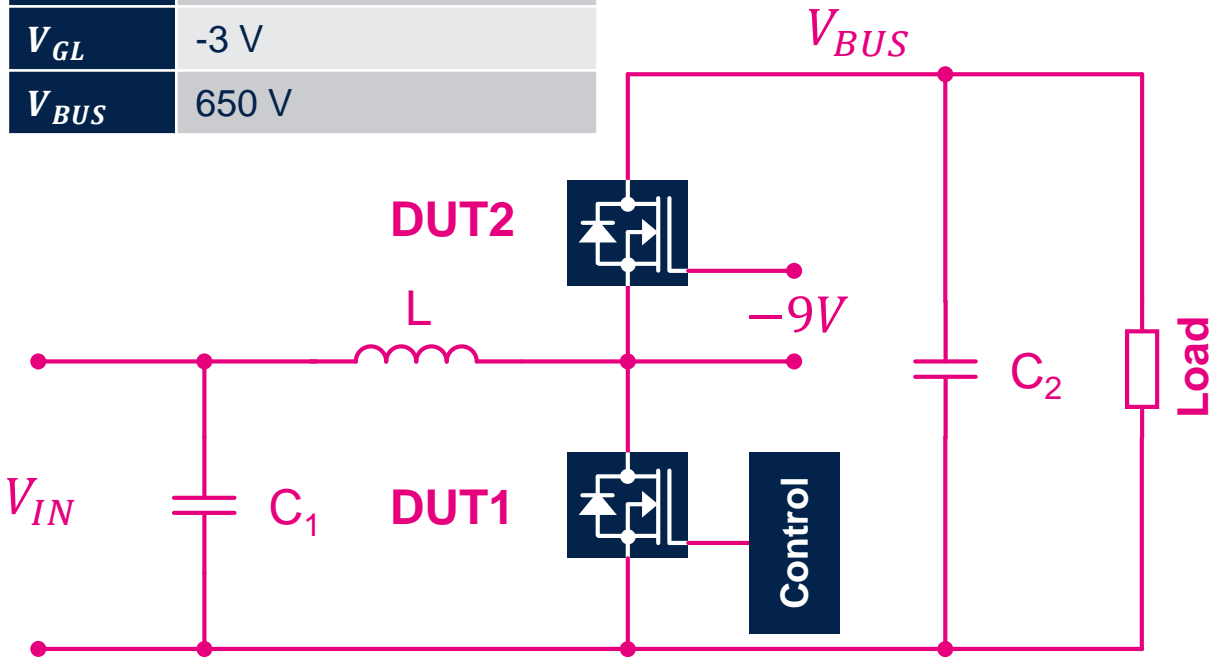
Turn-on transient



Turn-off transient

The switching energy is calculated by integrating the product of v_{DS} and i_S

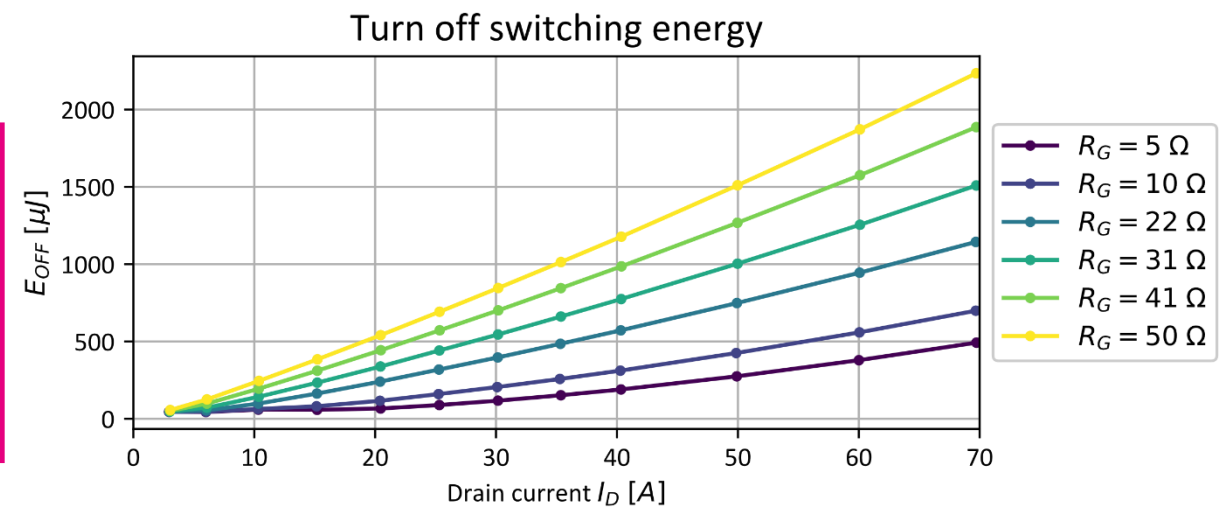
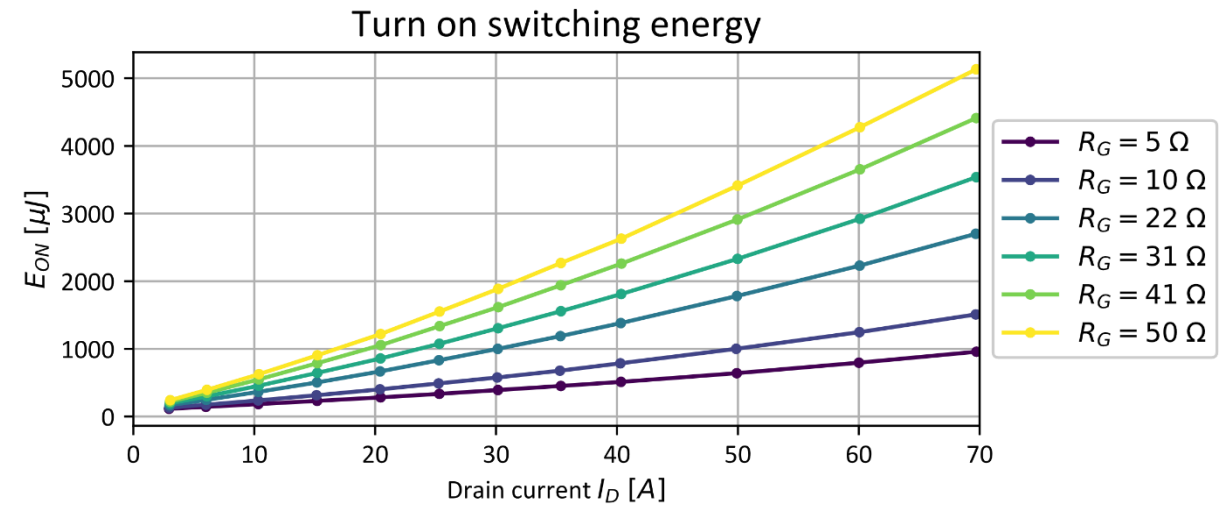
DUT1	SCTW60N120G2V-4
DUT2	SCTW60N120G2V-4
V_{GH}	18 V
V_{GL}	-3 V
V_{BUS}	650 V



As lower R_g as higher the switching speed \rightarrow higher EMI
 \rightarrow Lower R_g results in lower switching losses

Switching performance

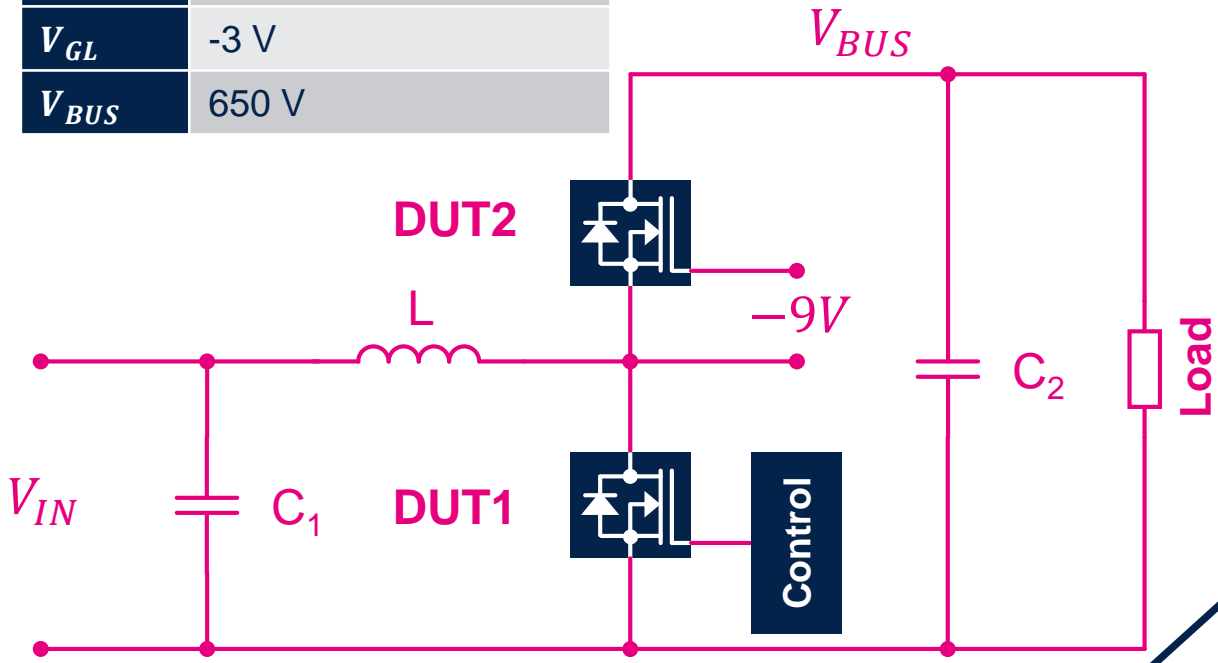
Switching energy



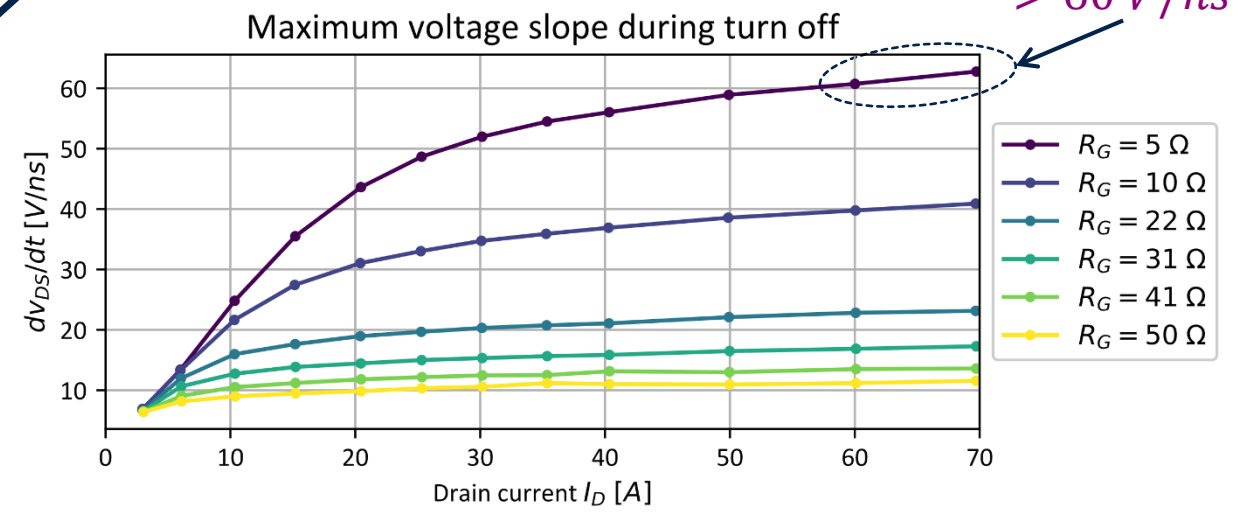
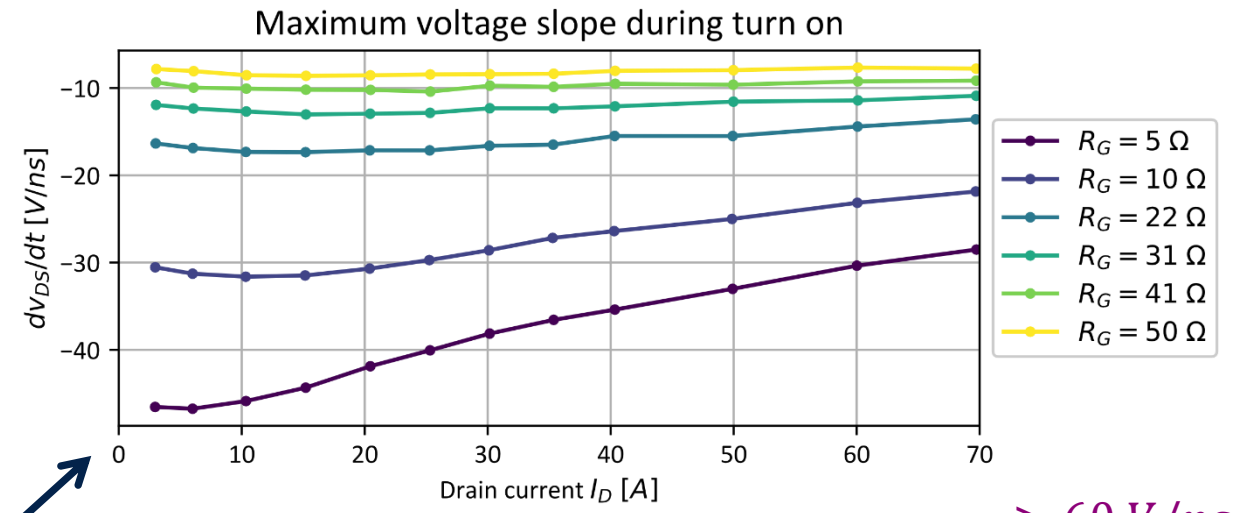
DUT1	SCTW60N120G2V-4
DUT2	SCTW60N120G2V-4
V_{GH}	18 V
V_{GL}	-3 V
V_{BUS}	650 V

Switching performance

Maximum voltage slope



High dv/dt immunity of gate driver is required

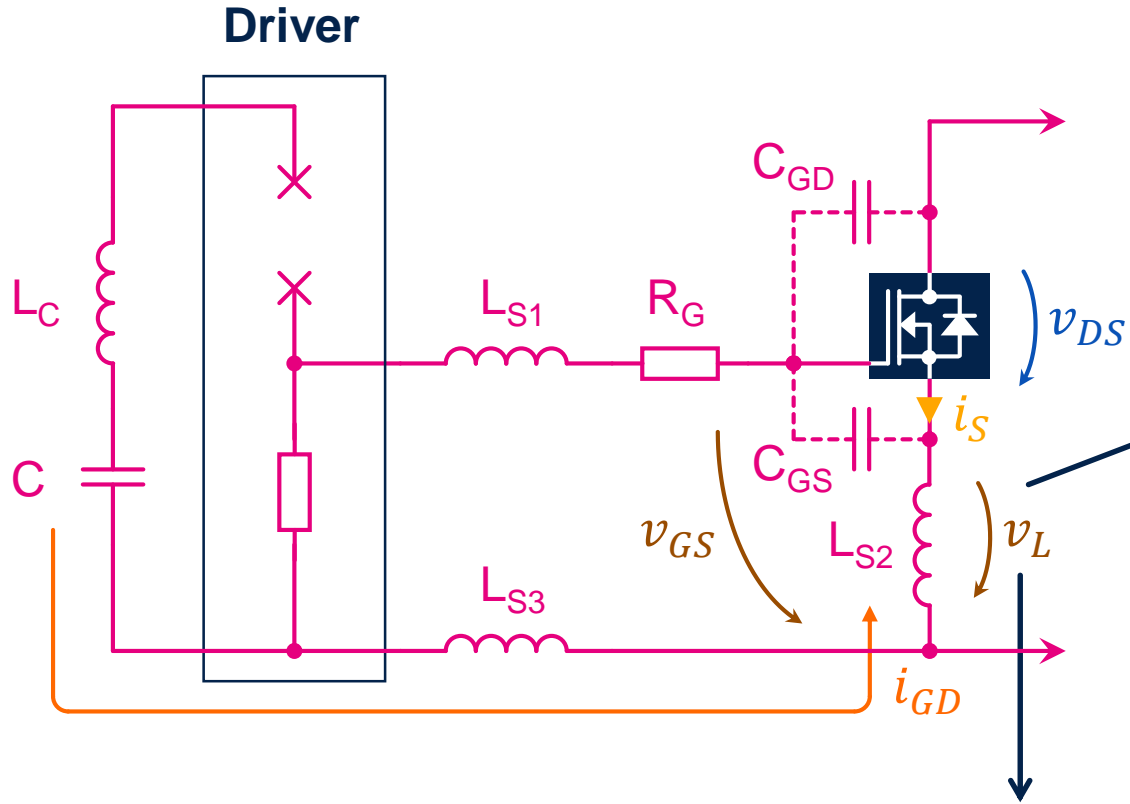


Standard vs. Kelvin source version



Turn off 3-pin vs. 4-pin Hard switching example

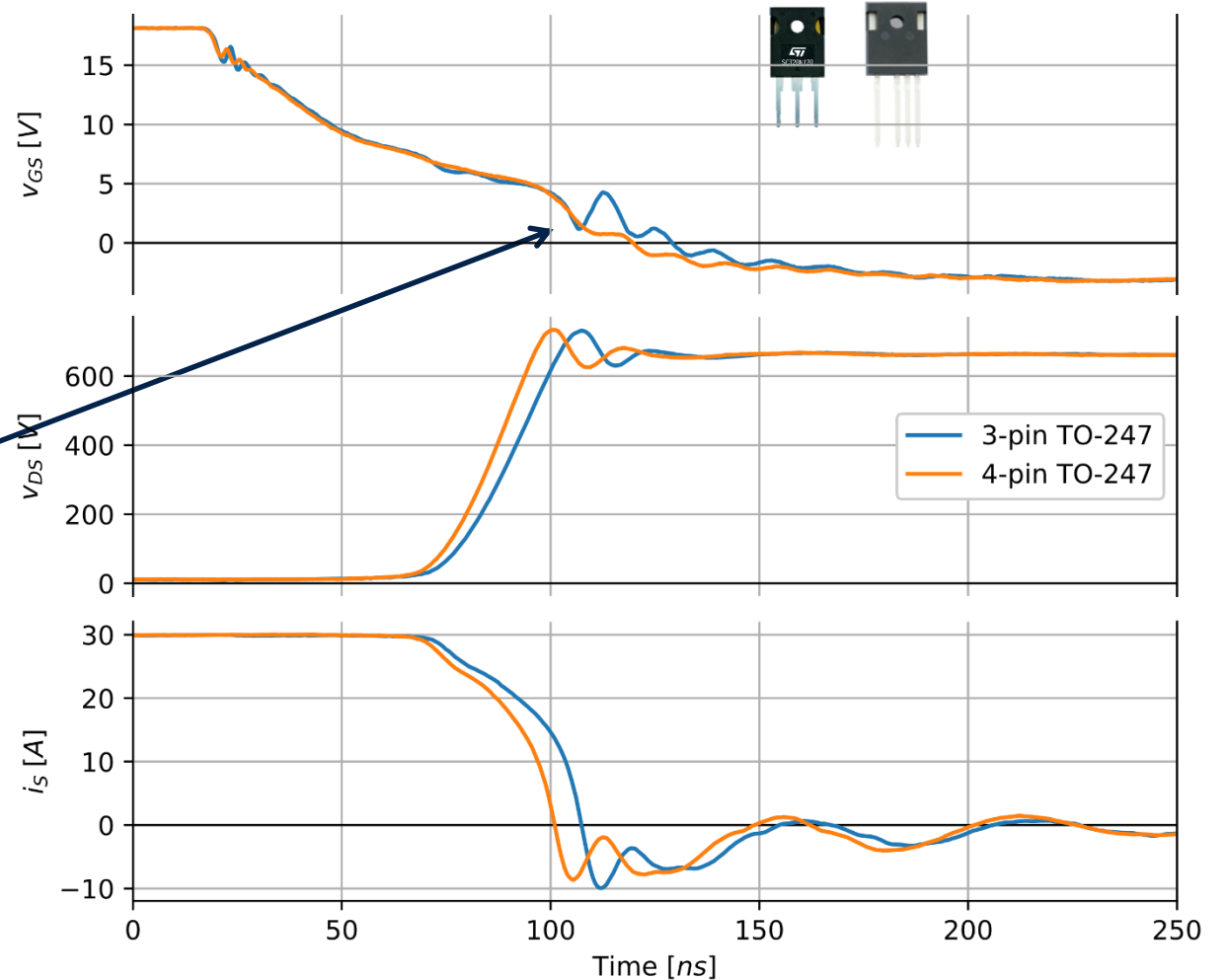
Higher turn off energy



$$v_L = L_{S2} \frac{di_S}{dt}$$

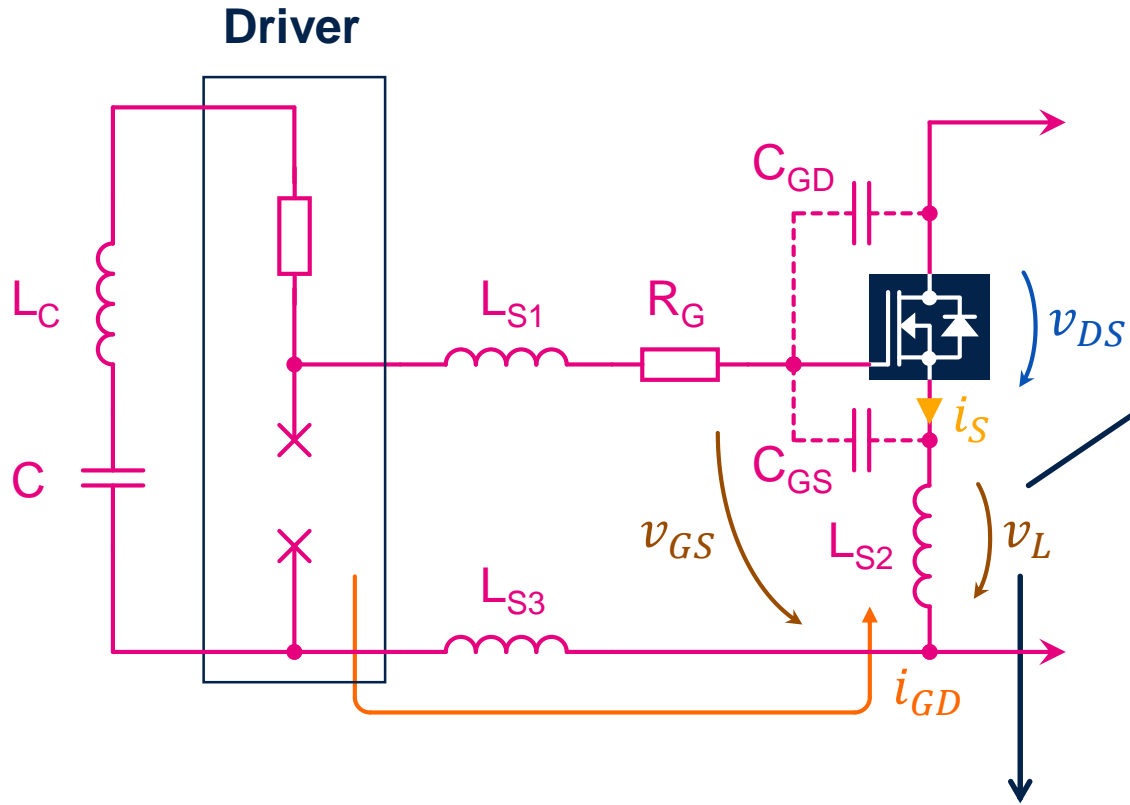
Voltage v_L slows down discharging of the C_{GS}

Turn off transient comparison of 3-pin and 4-pin package



Turn on 3-pin vs. 4-pin Hard switching example

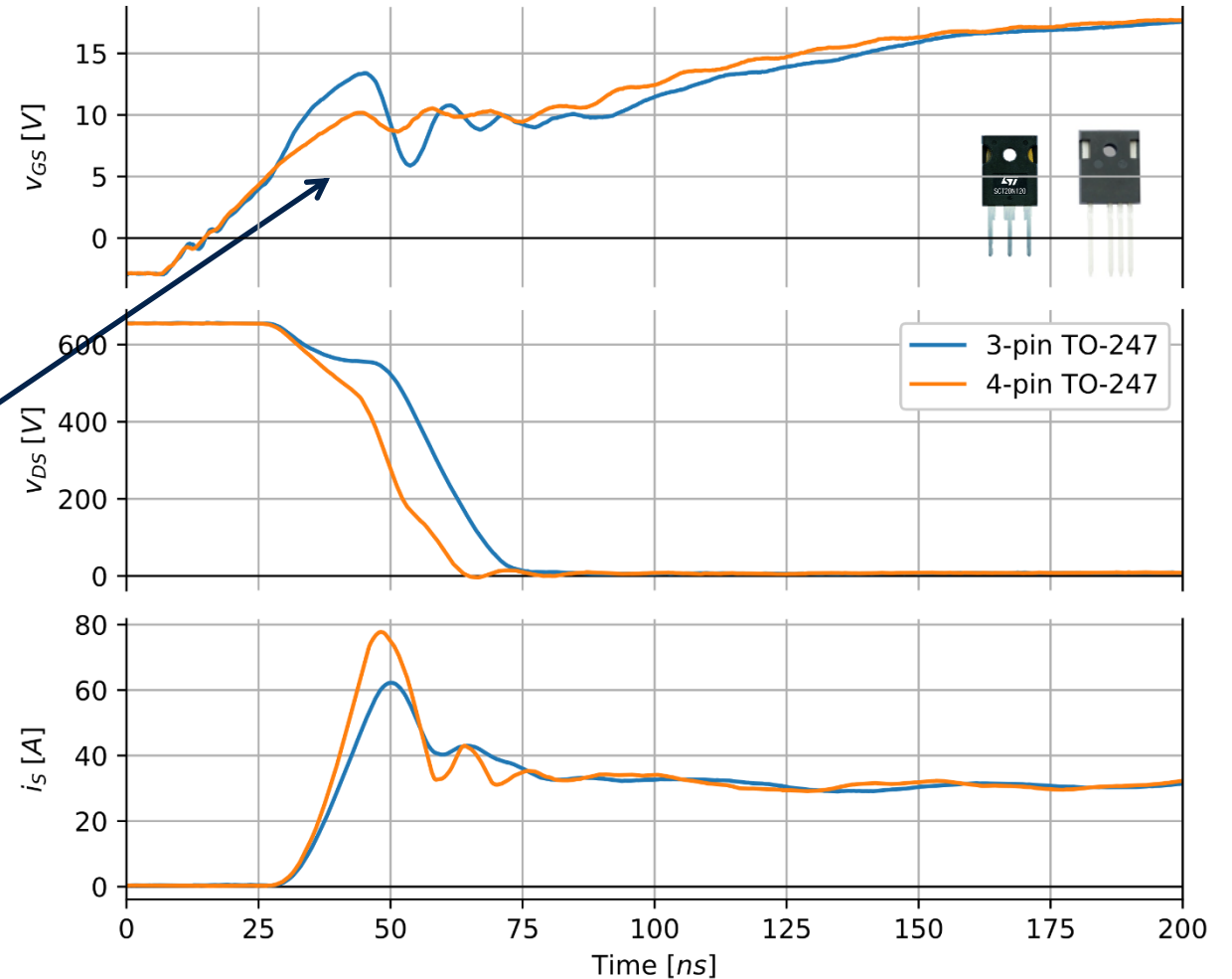
Higher turn on energy



$$v_L = L_{S2} \frac{di_S}{dt}$$

Voltage v_L slows down charging of the C_{GS}

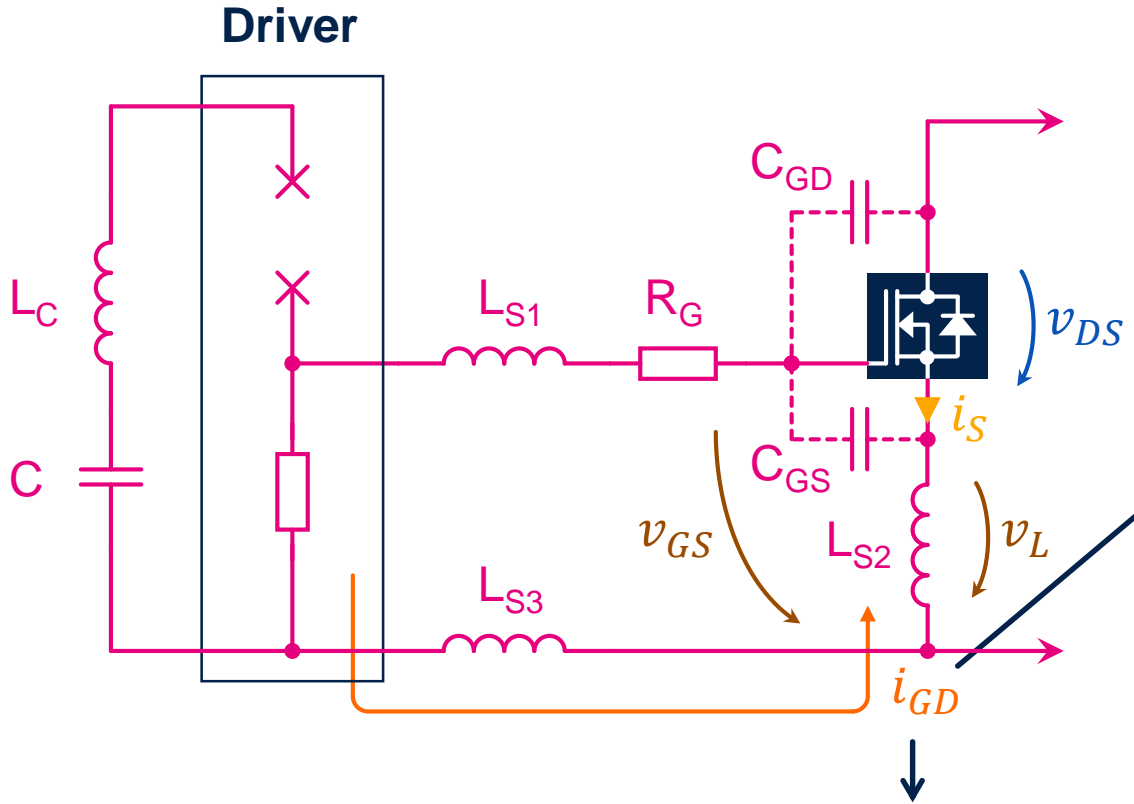
Turn on transient comparison of 3-pin and 4-pin package



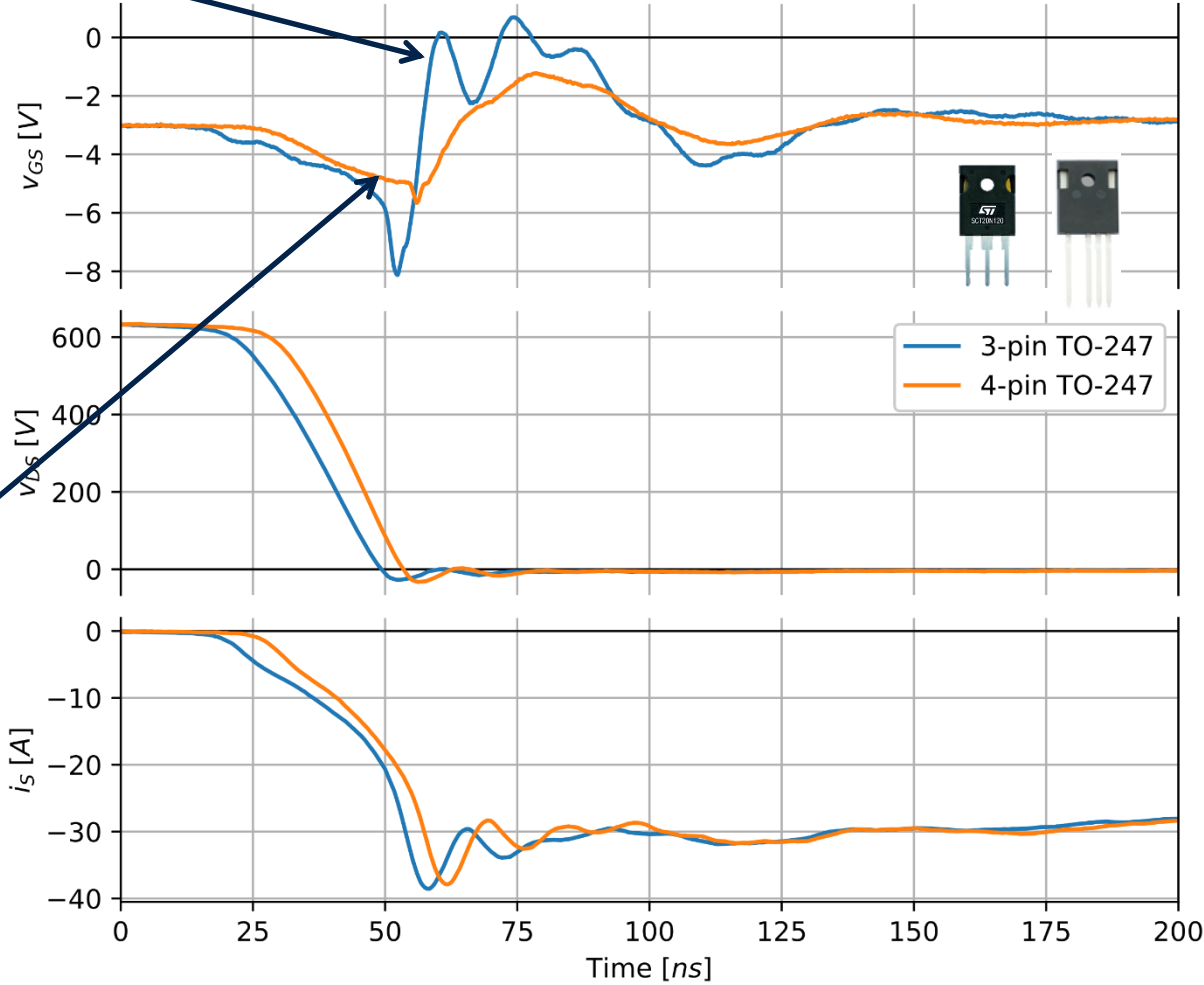
Pre turn on 3-pin vs. 4-pin Soft switching example

Risk of unwanted turn on

Turn on transient comparison of 3-pin and 4-pin package



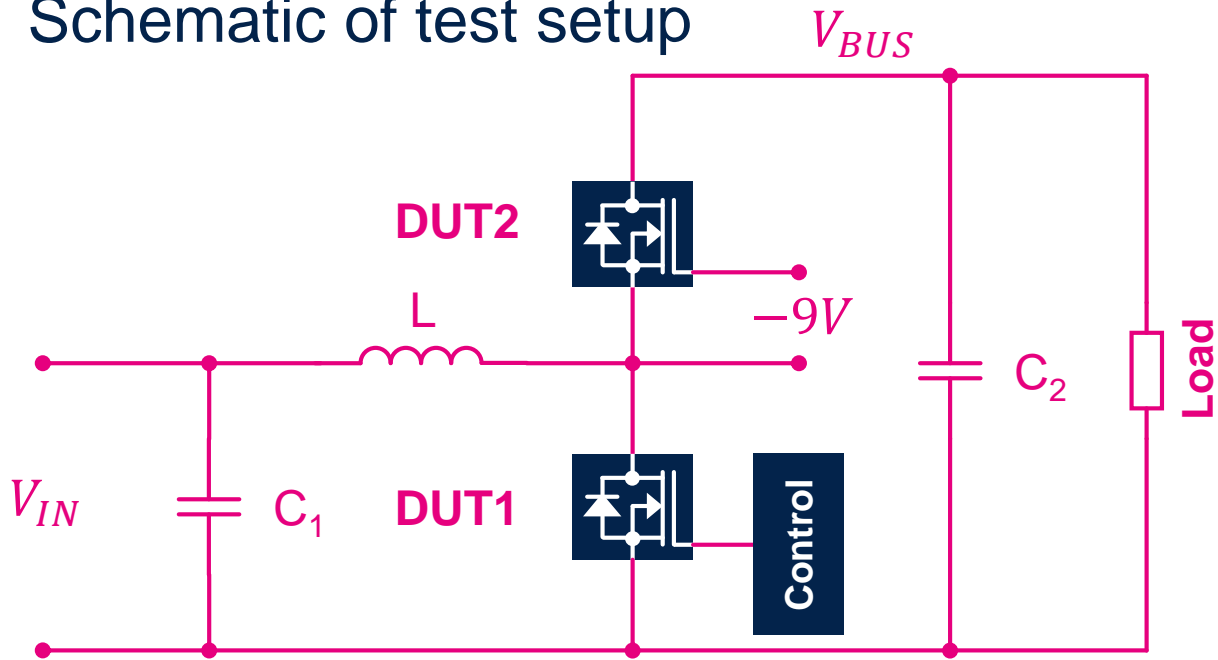
Induced oscillation inside the driving loop



Switching energy

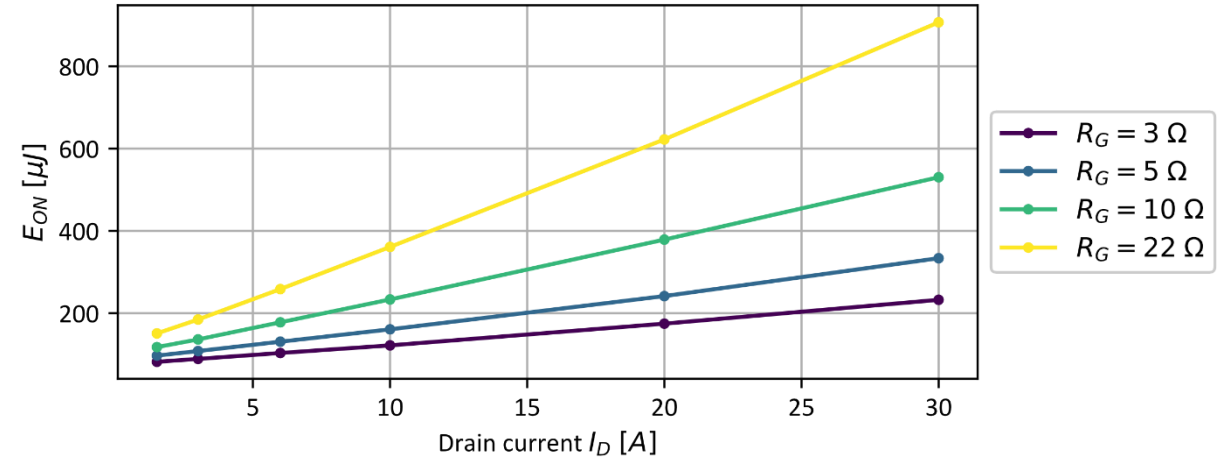
25 mΩ SiC MOSFET in 3-pin TO-247 package

Schematic of test setup

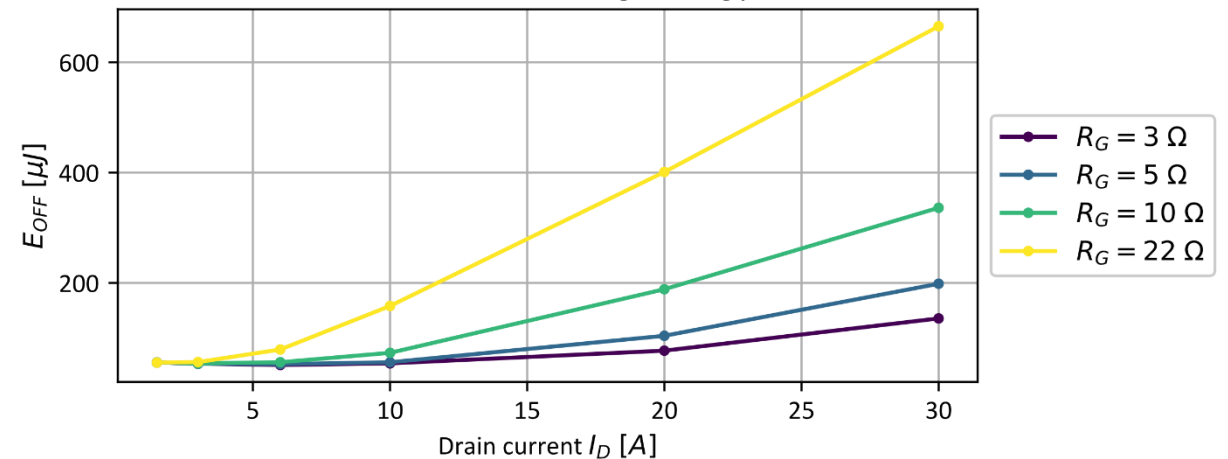


DUT1	SCTW70N120G2V
DUT2	SCTW70N120G2V
V_{GH}	18 V
V_{GL}	-3 V
V_{BUS}	600 V

Turn on switching energy

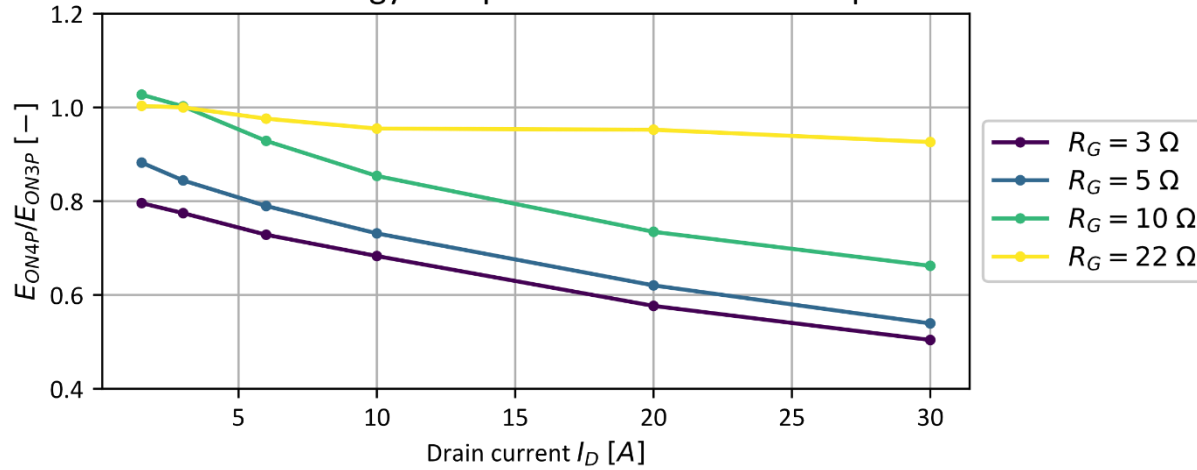


Turn off switching energy

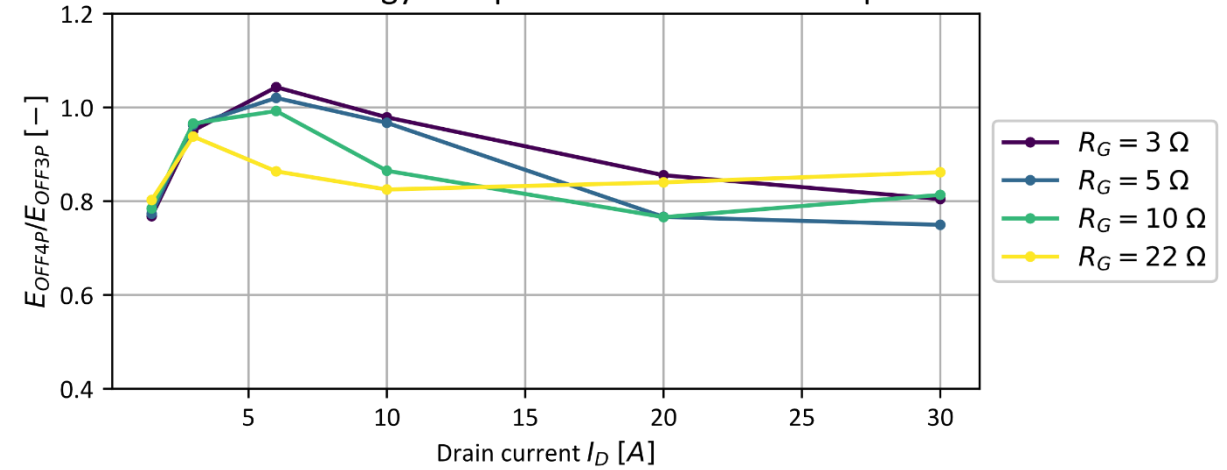


Switching energy Comparison of 3-pin and 4-pin package

Turn on energy of 4-pin version relative to 3-pin



Turn off energy of 4-pin version relative to 3-pin

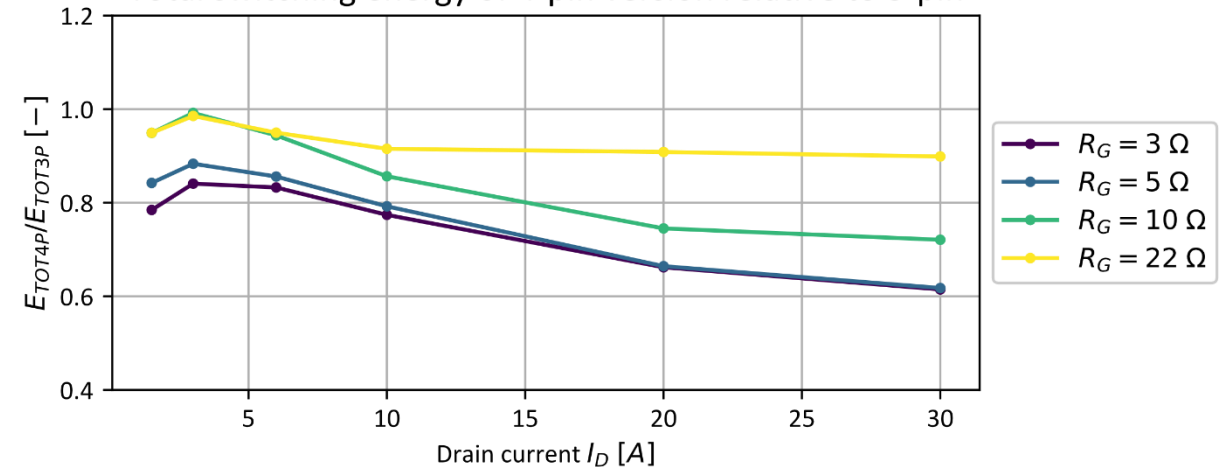


- 40% reduction of **switching** losses for lower R_G , and high I_D

	3-pin	4-pin
E_{ON} [μJ]	531	351
E_{OFF} [μJ]	336	274

$$I_D = 30 \text{ A}, R_G = 10 \Omega$$

Total switching energy of 4-pin version relative to 3-pin



SiC MOSFET Driving



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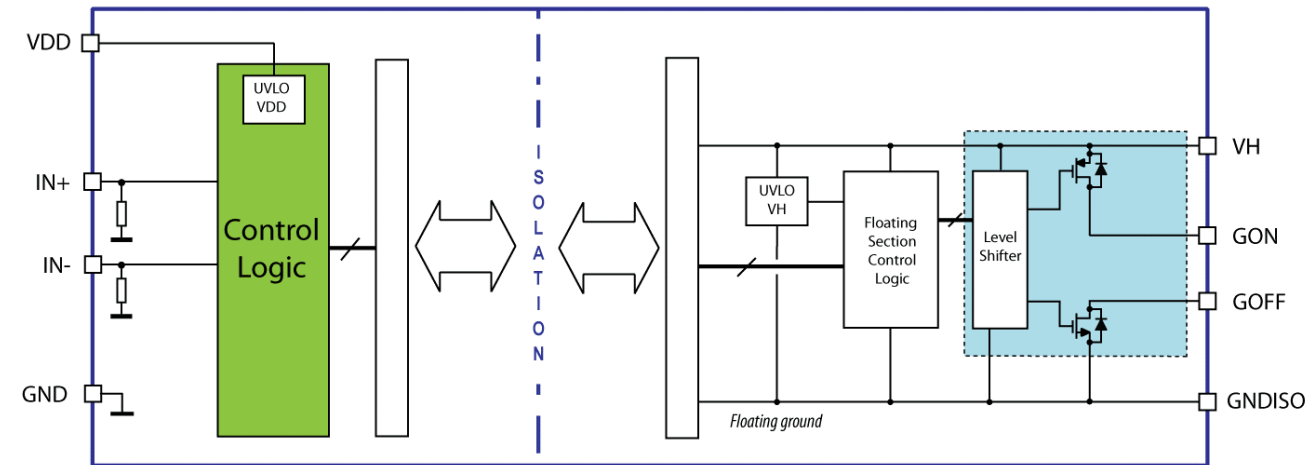
STGAP2S / STGAP2D

Galvanic isolated 4 A Single & Dual channel gate drivers

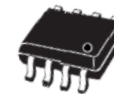
Born to drive Mosfet, IGBT and SiC
in High Power applications

Available in following versions:

- STGAP2D - Half-bridge Dual Channel
- STGAP2SM - Single Channel gate driver
- STGAP2SCM - Single Channel with Miller CLAMP pin
- Galvanic isolation
 - **1.7 kV** in standard **SO-8** package
 - **6 kV** in wide **SO-8W** package
- Up to **26 V** supply voltage
- Best in class for **propagation delay 80 ns**
- Minimum transient immunity ± 100 V/ns



SO-8N



In Production

SO-8W



2020

Main benefits

- Best in Class for **fast speed**
- **Reduced BOM** thanks to embedded Isolation and Miller Clamp feature
- **Minimum footprint** and lightweight

Associated Reference boards:

EVALSTGAP2DM
EVALSTGAP2SM
EVALSTGAP2SCM



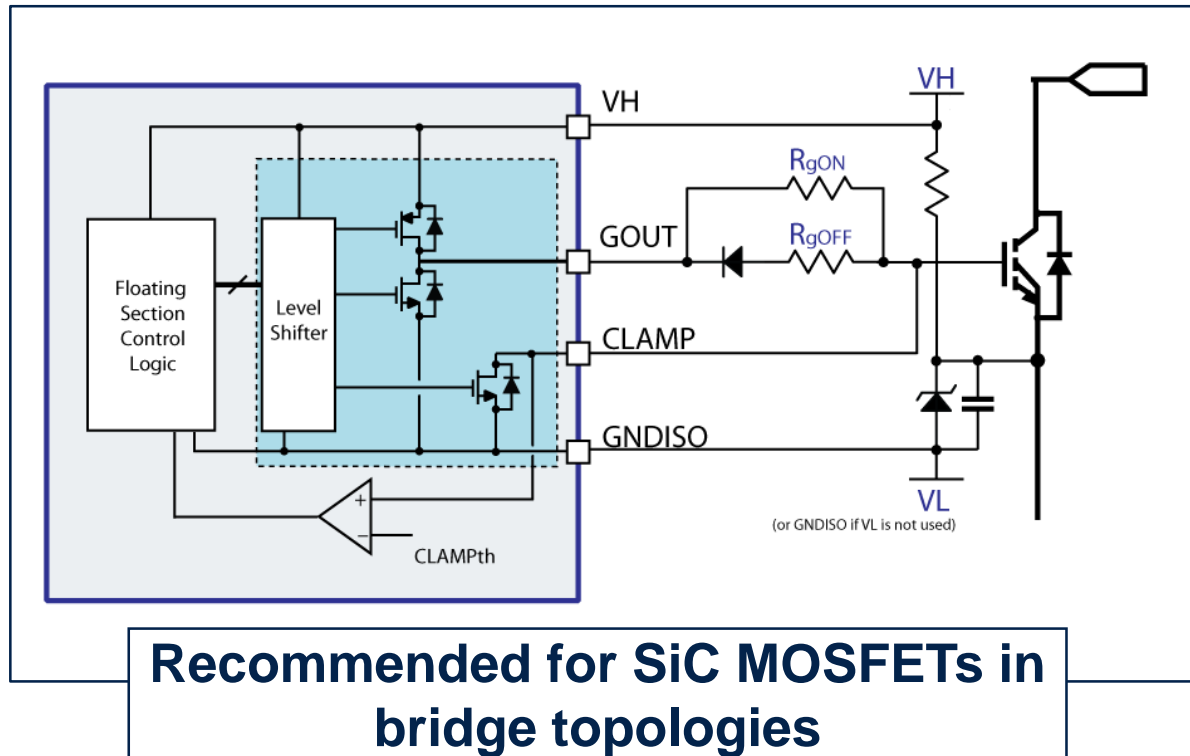
SO8 package



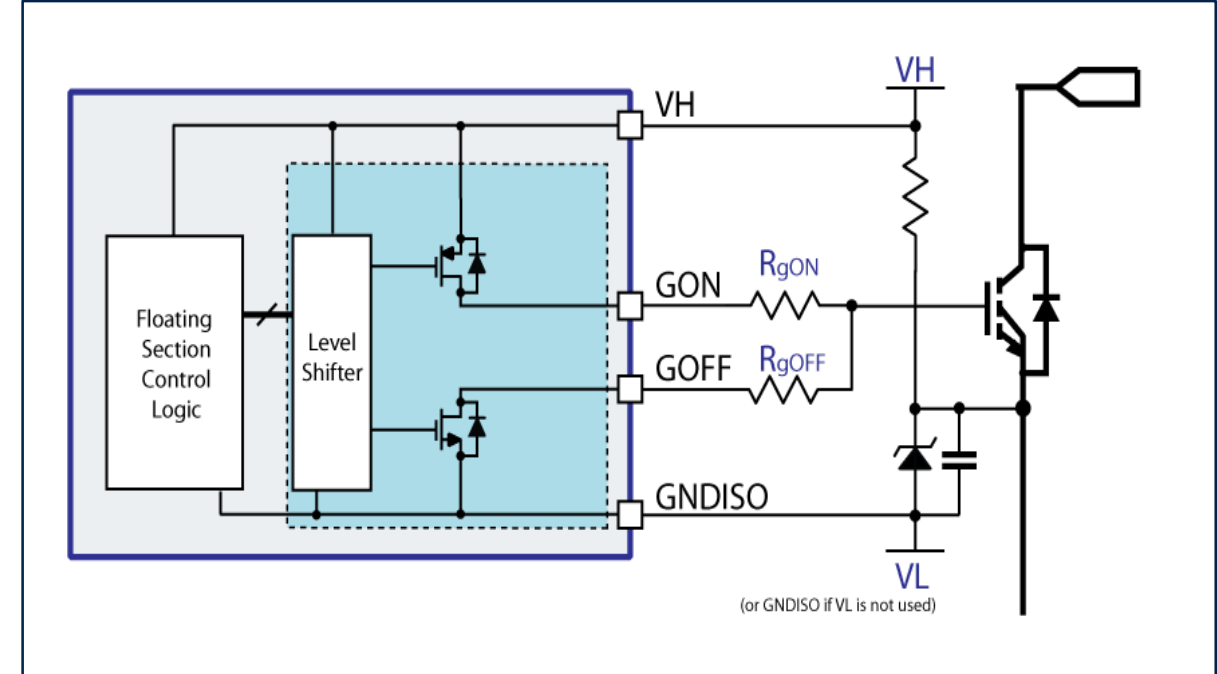
SO16 package

SiC MOSFET About Driving... STGAP2S

1700 V, 4A gate drivers



Option 1:
Single output and Miller CLAMP

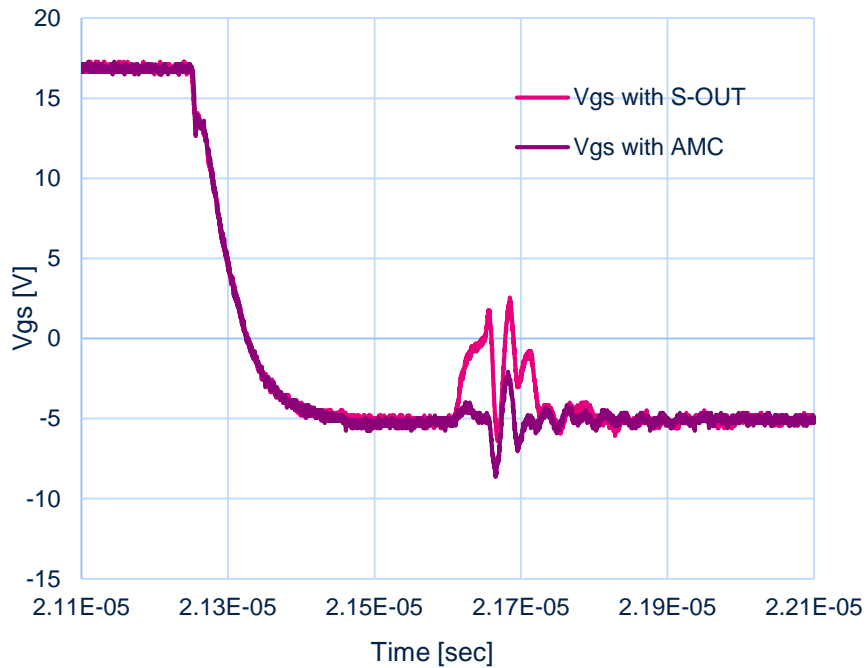


Option 2:
Separated sink/source outputs (no Miller Clamp)

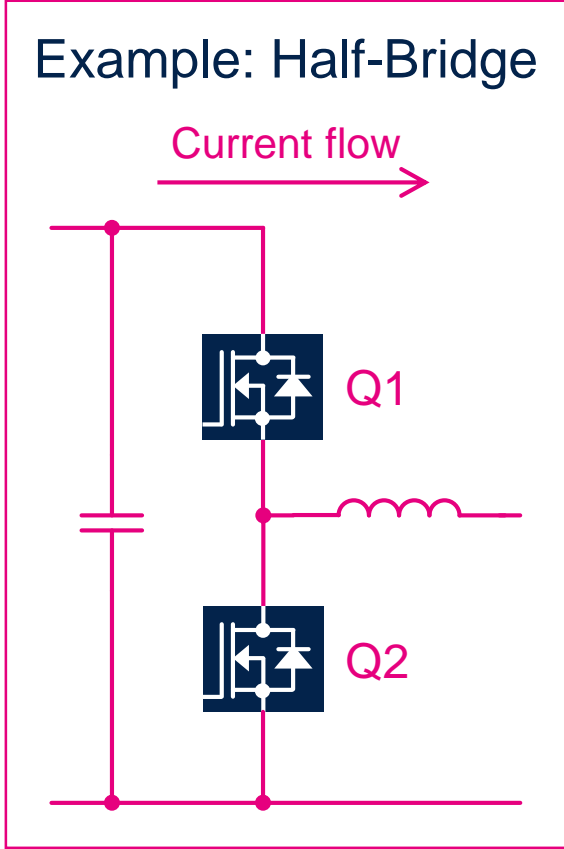
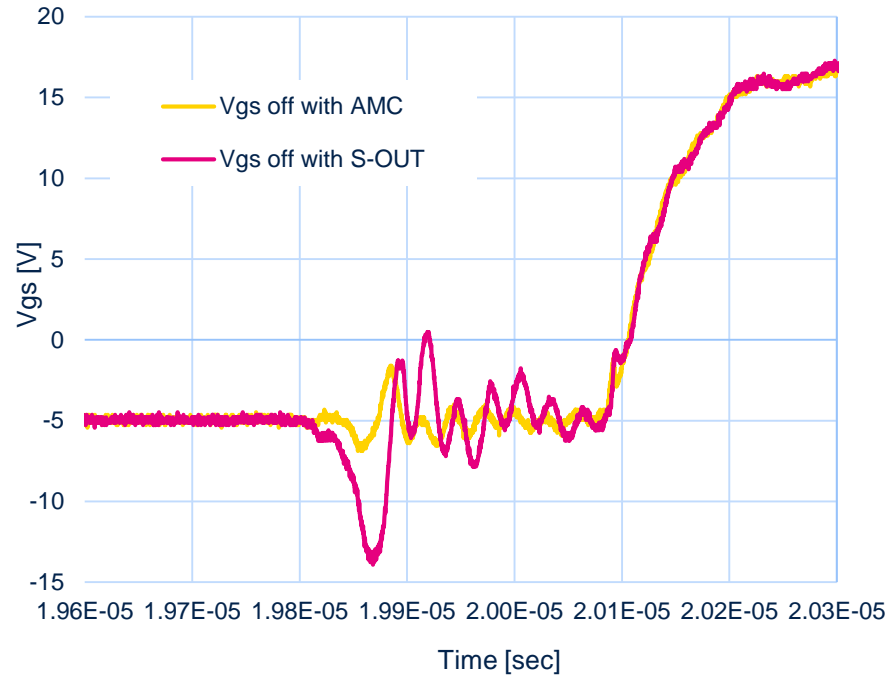
Dynamics: Advantages of Active Miller Clamp

SCTW35N65G2V
55 mΩ, 650 V SiC MOSFET

Positive Glitch



Negative Glitch



driver configuration

- **S-Out:** separated output (no Miller Clamp)
- **AMC:** Active Miller Clamp

$$V_{GH} = 18\text{ V}$$

$$V_{GL} = -5\text{ V}$$

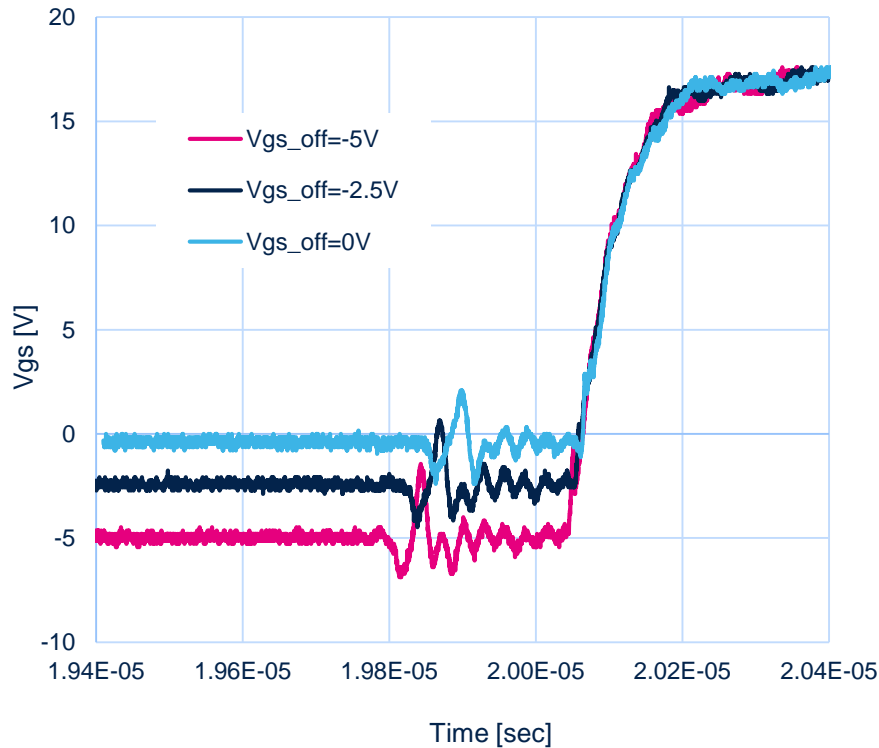
Active Miller Clamp is recommended for SiC MOSFETs in bridge topologies

SiC MOSFET

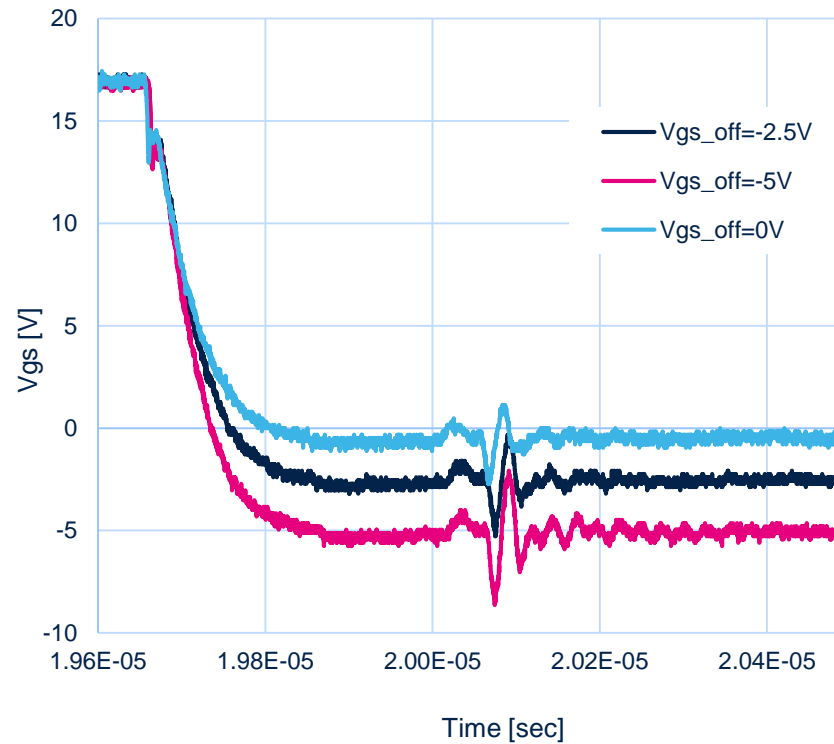
Extended V_{GS} max ratings for safe switching

SCTW35N65G2V
55 m Ω , 650 V SiC MOSFET

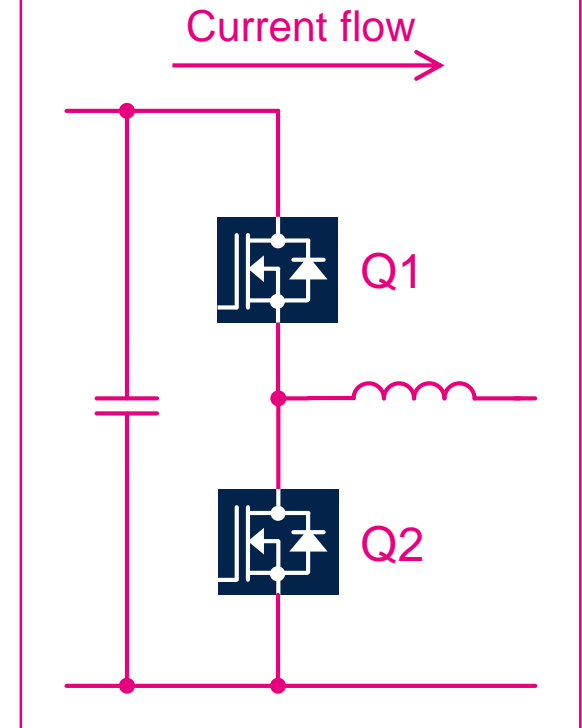
Positive Glitch



Negative Glitch



Example: Half-Bridge



Gate driver parameters

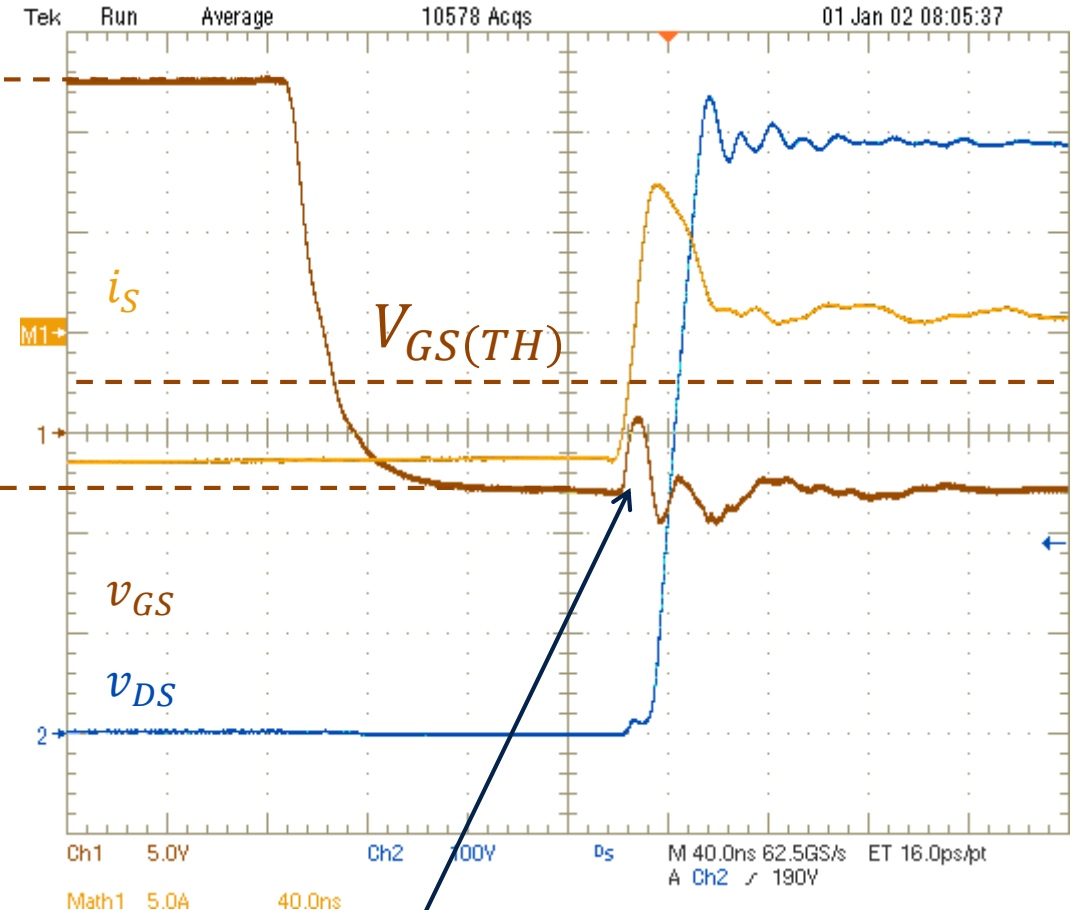
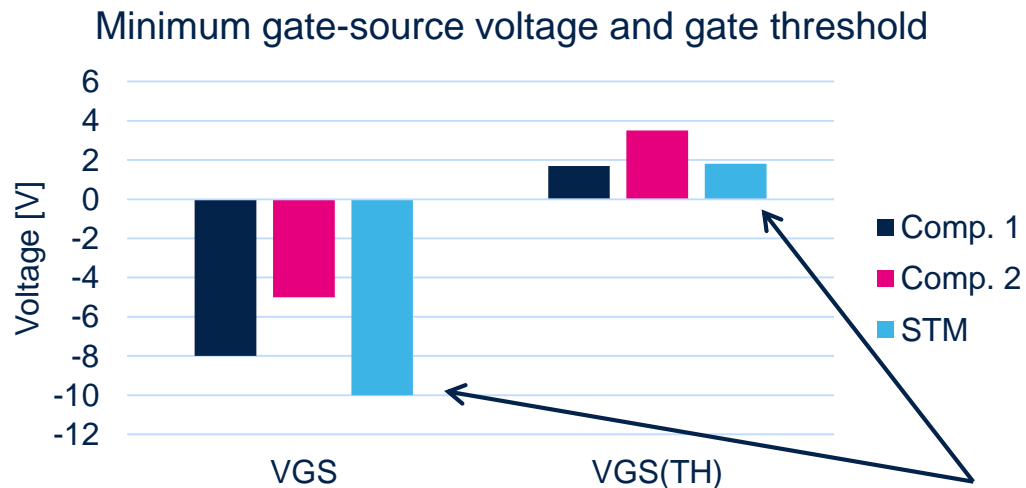
Summary of key points

$$V_{GS(on)} = 18 \text{ to } 20V,$$

- To get the best $R_{DS(on)}$

$$V_{GS(off)} = -3 \text{ to } -5V,$$

- Greater margin to the $V_{GS(TH)}$



Spikes might cause parasitic turn-on

Higher negative voltage can be applied

Summary

- Driving a SiC MOSFET is almost easy as driving a silicon MOSFET:
 - ST suggest using recommended V_{gs} , like 18V to get the right $R_{DS(on)}$
 - Adequate current capability to ensure high switching speed
- Turn-off a SiC MOSFET with Negative driving voltage :
 - Negative voltage is suggested only for bridge topologies to avoid any possible undesired turn-on due to gate voltage oscillations (Miller turn-on effect).
 - The negative voltage (in the range [-6V,-2V]) has an impact on the turn-off switching losses reduction. This of course will depend on the sinking current driver's capability.
 - To turn-off with a few negative volts (-6V is the minimum recommended) in order to not exceed the max.
- The main aspects influencing switching behavior are:
 - Turn-off energy (E_{off}) dependence on R_g and V_{GS-off} (negative bias gate voltage)
 - Turn-on energy (E_{on}) dependence on R_g
 - Miller effect, which affects E_{on} and E_{rr} (reverse recovery energy)
 - Gate drive current requirements

New SiC related evalboards



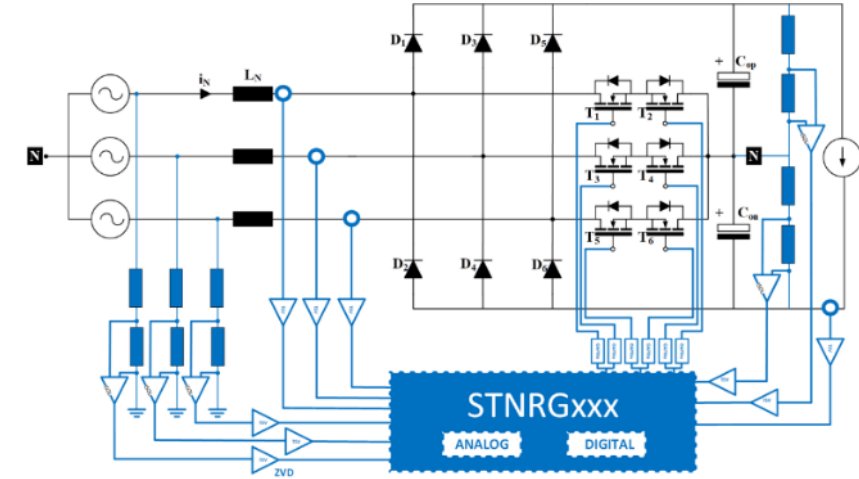
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15kW VIENNA Rectifier

ST Demoboard: STDES-VIENNARECT

Main specs

- 3-phase, 3-level AC/DC power converter
- Rated nominal output DC voltage: 800 VDC
- Rated nominal input AC voltage: 400 VAC at 50 Hz
- Nominal output power AC/DC: 15 kW
- Power factor, **PF>0.99**
- Inrush current control and soft start-up
- THD lower than 5% at nominal operation
- Power section based on SiC MOSFETs and diodes:
- High frequency operation (70 kHz)
- **High peak efficiency greater than 98%**
- Passive element weight and size reduction



15kW Power board



Control board

Key products

- **STNRGPF03*** (Digital controller for 3Ph PFC)
- **SCTW35N65G2V** (6x SiC MOSFET)
- **STGAP2S** (Galvanic Isolated Gate Driver)
- **STPSC20H12D** (SiC diodes), **STPS1L30A**, **STPS2H100A**, **STTH1L06A**, **STPS1150A**, **STPS2L60A** (Schottky and Ultrafast diodes)
- **VIPer26HD** (High Voltage Converter)

*Under Development

4 Layer PCB (40x36 cm)

15kW 3L T-Type Converter PFC

ST Demoboard: STDES-PFCBIDIR

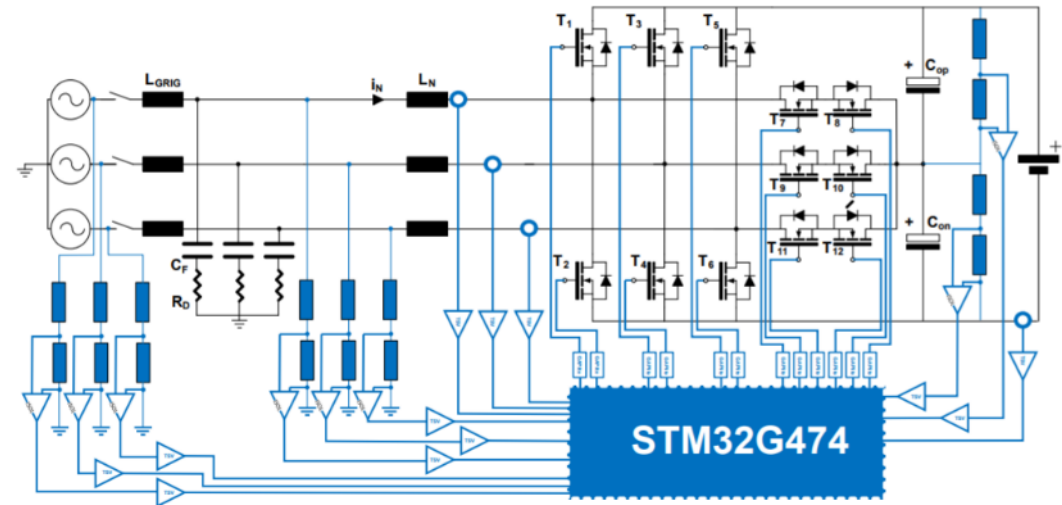
Main specs

- $P_{out} = 15kW$ @ $V_{in} = 380Vac$ & $V_{out} = 800V$
- $PF > 0.98$ @ 20% load (target)
- $THD < 5\%$ @ 20% load (target)
- $\eta > 99\%$
- CCM decoupling current control loop
- Active & Reactive power control
- Grid Connection capability
- Switching frequency = 100kHz
- $I_{ripple} = 2.5A$
- $VDC_{ripple} = 10V_{pp}$

Key products

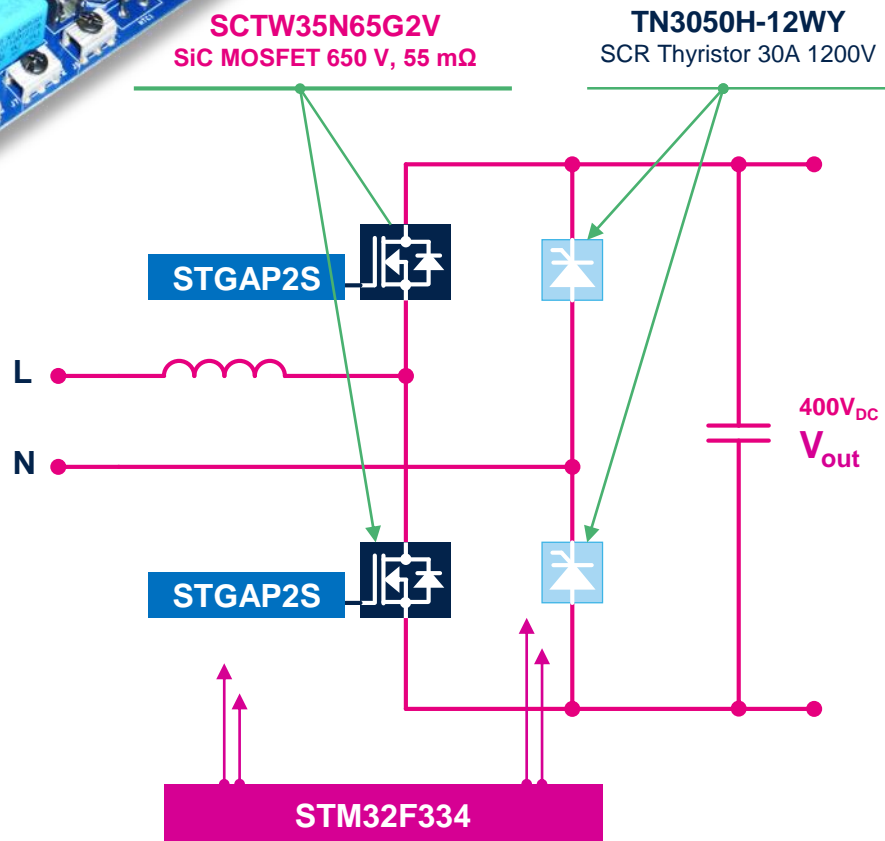
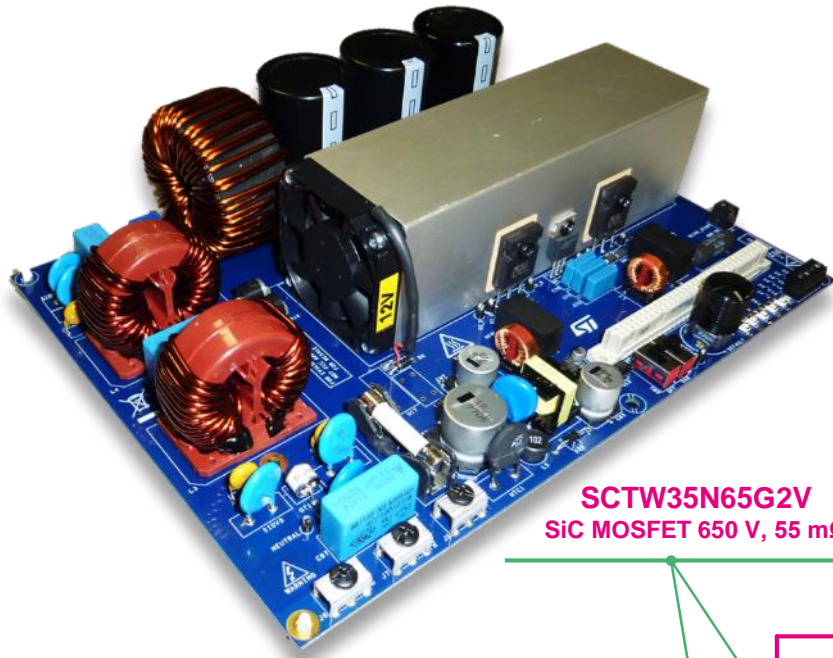
- **SCTW40N120G2V** (6x 70m Ω 1200V SiC MOSFET)
- **SCTW35N65G2V** (6x 55m Ω 650V SiC MOSFET)
- **STGAP2S** (Galvanic Isolated Gate Driver)
- STPS1L30A, STPS2H100A, STTH1L06A, STPS1150A, STPS2L60A (SiC, Schottky and Ultrafast diodes)
- STS6NF20V (N-channel 20 V, STripFET II Power MOSFET)
- TSV911IDT, TSV912IDT, TSV914IDT (wide-bandwidth rail to rail Op-Amps)
- STLM20W87F (Analog temperature sensor)
- LD29080DT50R, LD29080S33R, (LDOs)
- VIPer26K (High Voltage Converter)

Figure 1. Bidirectional converter block diagram



STEVAL-DPSTPFC1

3.6 kW 1-ph Totem-Pole PFC



- Input AC voltage: **85 V_{AC} up to 264 V_{AC}**
- Input AC frequency: 45 Hz up to 65 Hz
- DC output voltage: **400 V_{DC}**
- Maximum input current: **16 A_{RMS}**
- Ambient temperature: tested from 0 °C up to 45 °C
- Peak Efficiency: **97.7 %** with **4.7% THD**
- Compliant with:
 - EN 55015 and IEC 61000-4-11 and IEC 61000-3-3
 - IEC 61000-4-5 surge: 4 kV
 - IEC 61000-4-4 EFT burst: criteria A @ 4 kV min
- Cooling: forced air cooling with active fan
- Designed for operation with DC / DC converter
- Peak **inrush** current tuning

ST SiC MOSFET/Diode support tools



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SiC Diode support tools

- Application Notes
 - AN4242 – New generation of 650 V SiC diodes
 - https://www.st.com/content/ccc/resource/technical/document/application_note/2c/90/d1/db/92/da/49/92/DM00075656.pdf/files/DM00075656.pdf/jcr:content/translations/en.DM00075656.pdf
 - AN5088 - Rectifiers thermal management, handling and mounting recommendations
 - https://www.st.com/resource/en/application_note/dm00437554.pdf
 - AN5436 - Thermal behavior and printed circuit board assembly recommendations for STMicroelectronics PowerFLAT 8x8 HV package
 - https://www.st.com/content/ccc/resource/technical/document/application_note/group1/01/52/a9/72/04/31/46/44/DM00676401/files/DM00676401.pdf/jcr:content/translations/en.DM00676401.pdf
- Simulation Models
 - Silicon-carbide (SiC) Schottky diode PSpice models (.lib & .olb)

Overview	Tools & Software	Resources	Quality & Reliability
Quick links			
Product Specifications		Application Notes	Technical Notes & Articles
HW Model, CAD Libraries & SVD		Presentations	Flyers
Selection Guides		Brochures	Conference Papers



SiC MOSFET support tools

- **Application Notes**

- AN3152 – The right technology for solar converters
 - https://www.st.com/resource/en/application_note/cd00264004.pdf
- AN5355 - Mitigation technique of the SiC MOSFET gate voltage glitches with Miller clamp
 - https://www.st.com/resource/en/application_note/dm00628522.pdf
- AN4671 - How to fine tune your SiC MOSFET gate driver to minimize losses
 - https://www.st.com/resource/en/application_note/dm00170577.pdf

- **STPOWER MOSFET finder mobile App for tablets and smartphones (Apple Store, Google Play, Wandoujia)**

- https://www.st.com/content/st_com/en/products/mobile-applications/finders-apps/st-mosfet-finder.html

- **Simulation Models**

- SiC MOSFET PSpice models (.lib & .olb)

HW Model, CAD Libraries & SVD

HW MODEL, CAD LIBRARIES & SVD

	Description	Version	Size	Action
<input type="checkbox"/>	SCT10N120 PSpice model	1.0	5.29 KB	ZIP



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